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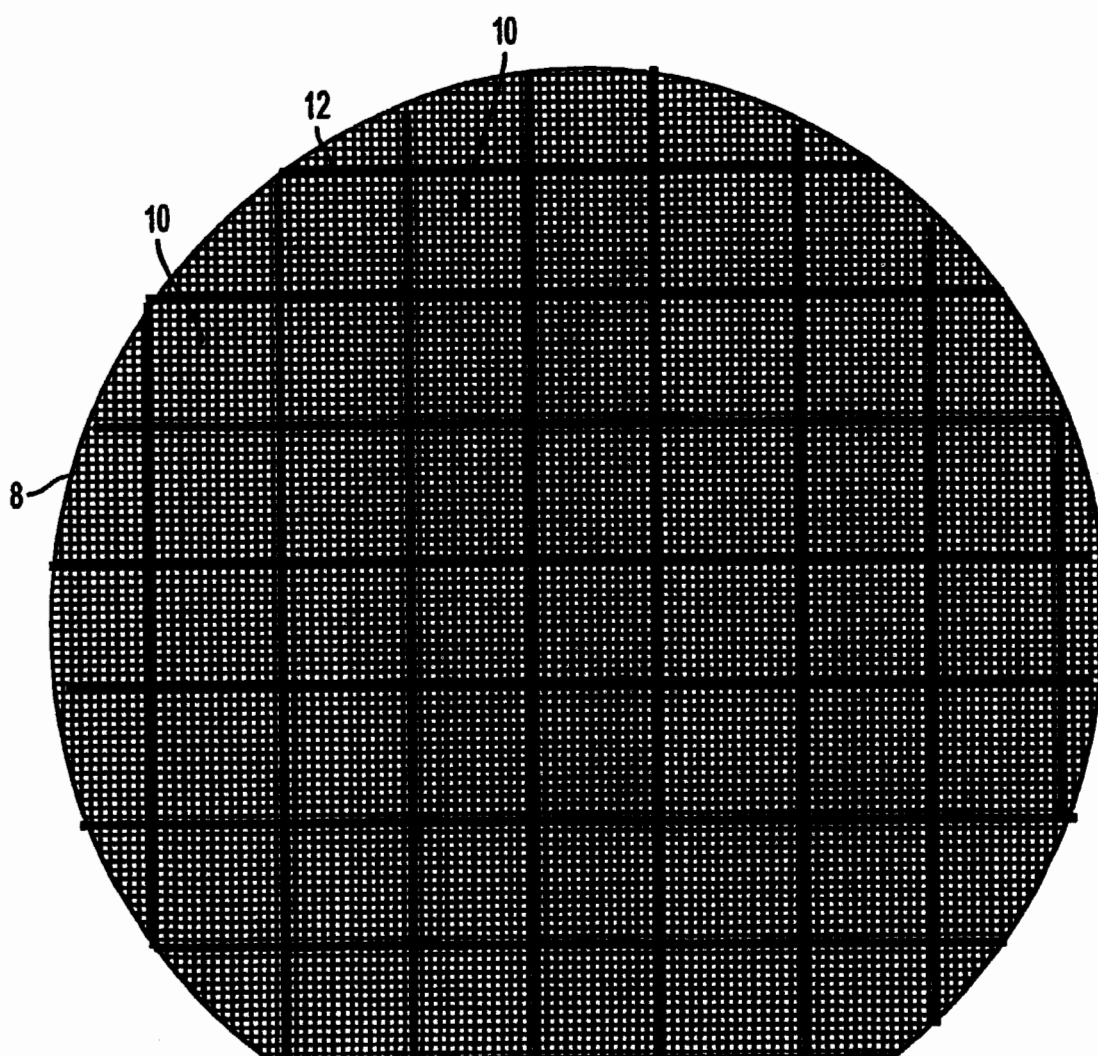


FIG. 1

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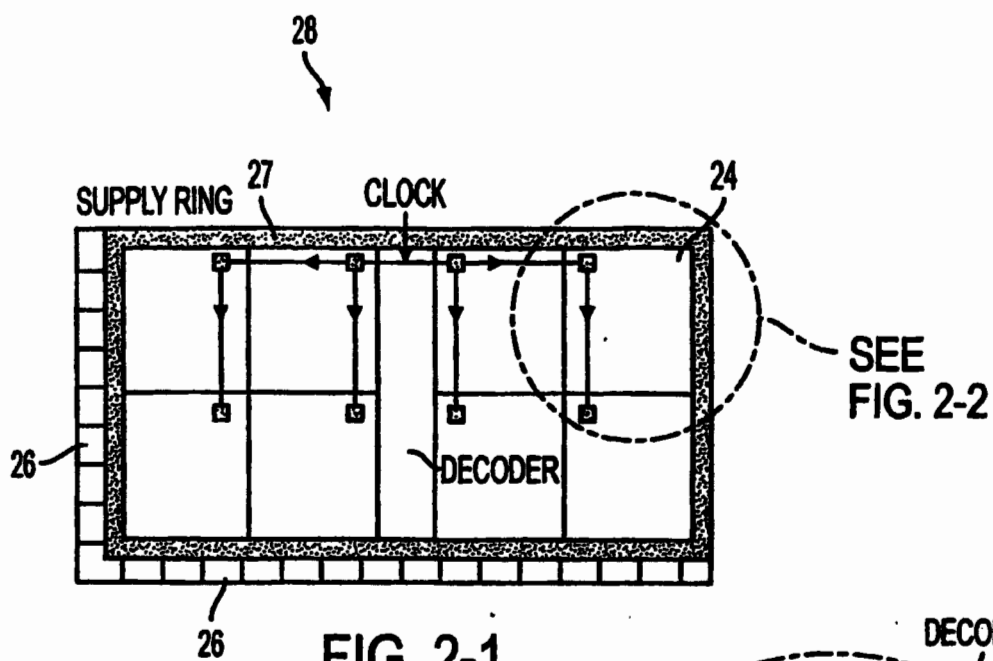


FIG. 2-1

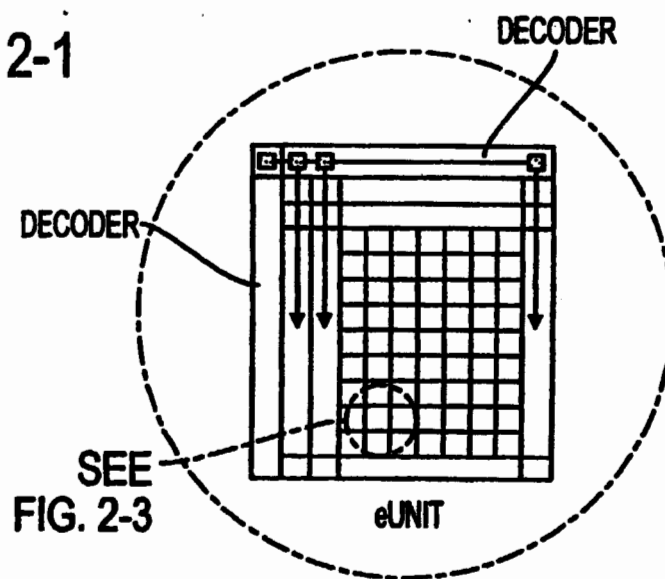


FIG. 2-2

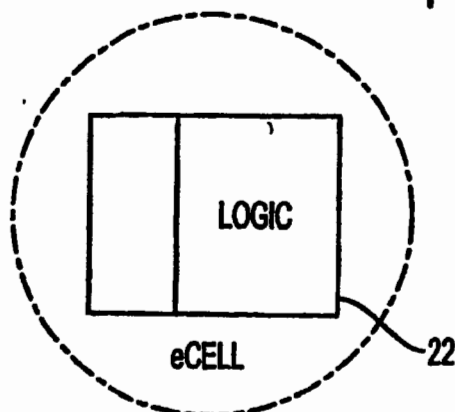


FIG. 2-3

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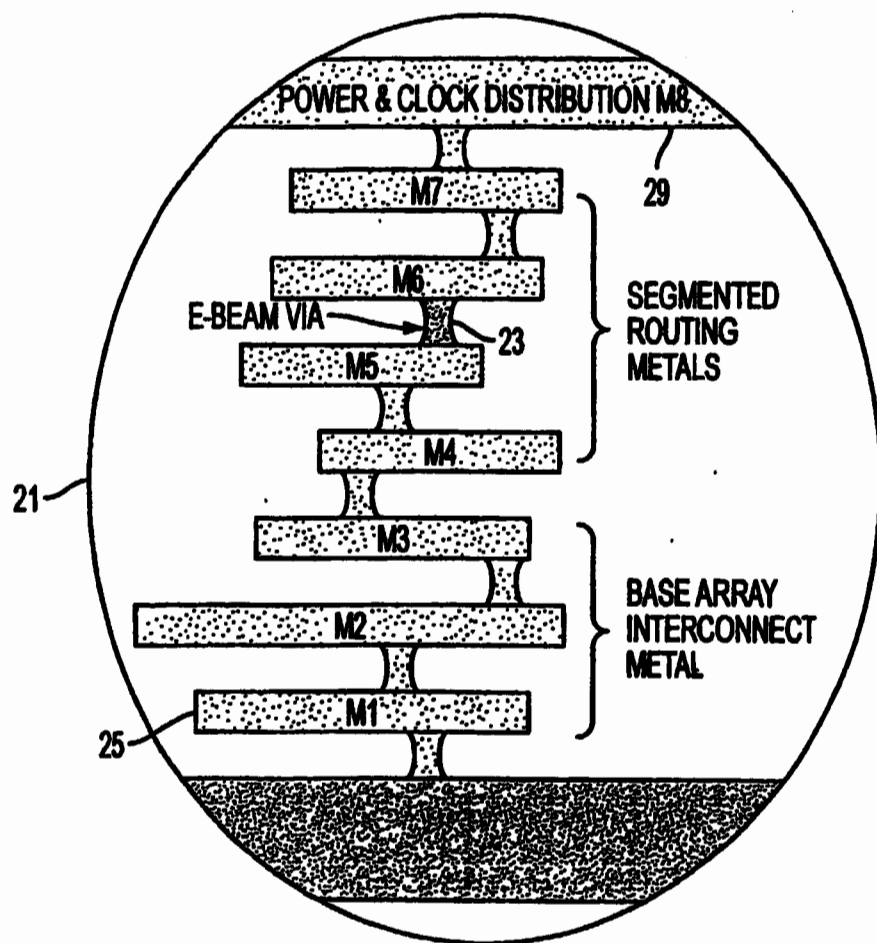


FIG. 2A

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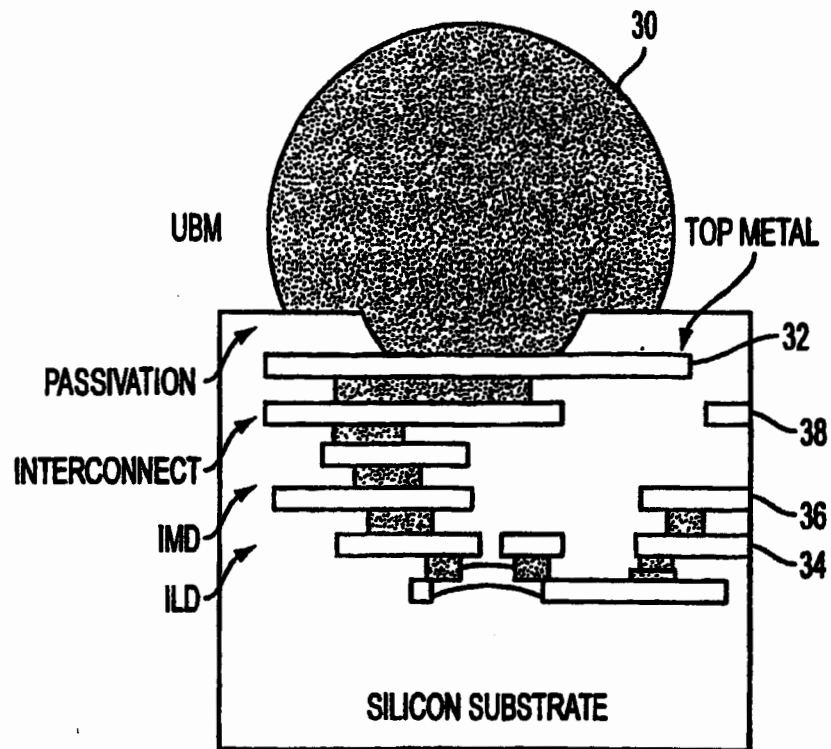


FIG. 3A

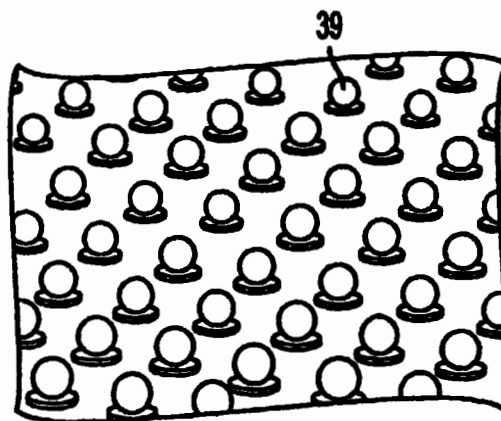


FIG. 3B

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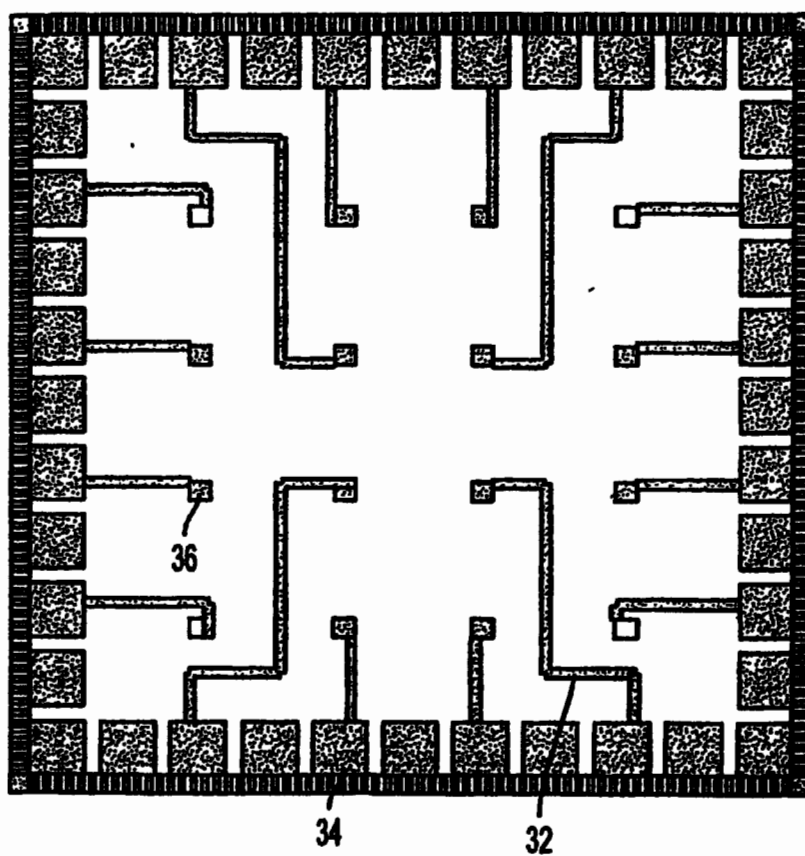


FIG. 3C

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B	BUMP DIAMETER	$150\mu\text{m} \pm 10\mu\text{m}$ (IN WAFER)	$70\mu\text{m} \pm 10\mu\text{m}$ (IN WAFER)
C	Cu BUMP HEIGHT	$20\mu\text{m} \pm 3\mu\text{m}$ (IN WAFER)	$10\mu\text{m} \pm 3\mu\text{m}$ (IN WAFER)
D	BUMP ROOT DIAMETER	$90\mu\text{m}$	$60\mu\text{m}$
E	PASSIVATION HOLE SIZE	$70\mu\text{m}$	$40\mu\text{m}$
F	BUMP PITCH	$200\mu\text{m}$	$120\mu\text{m}$

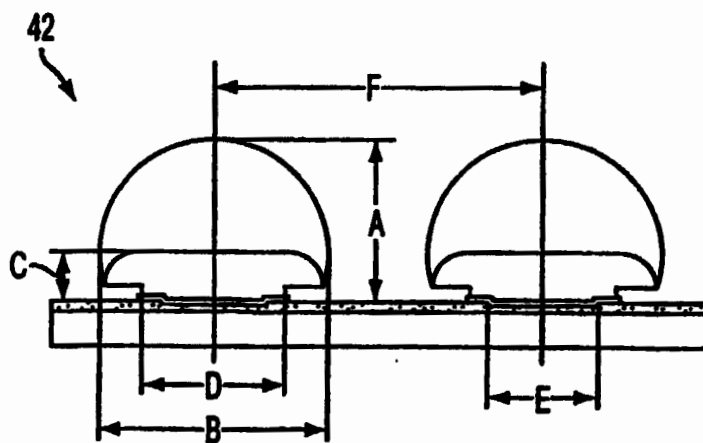


FIG. 4

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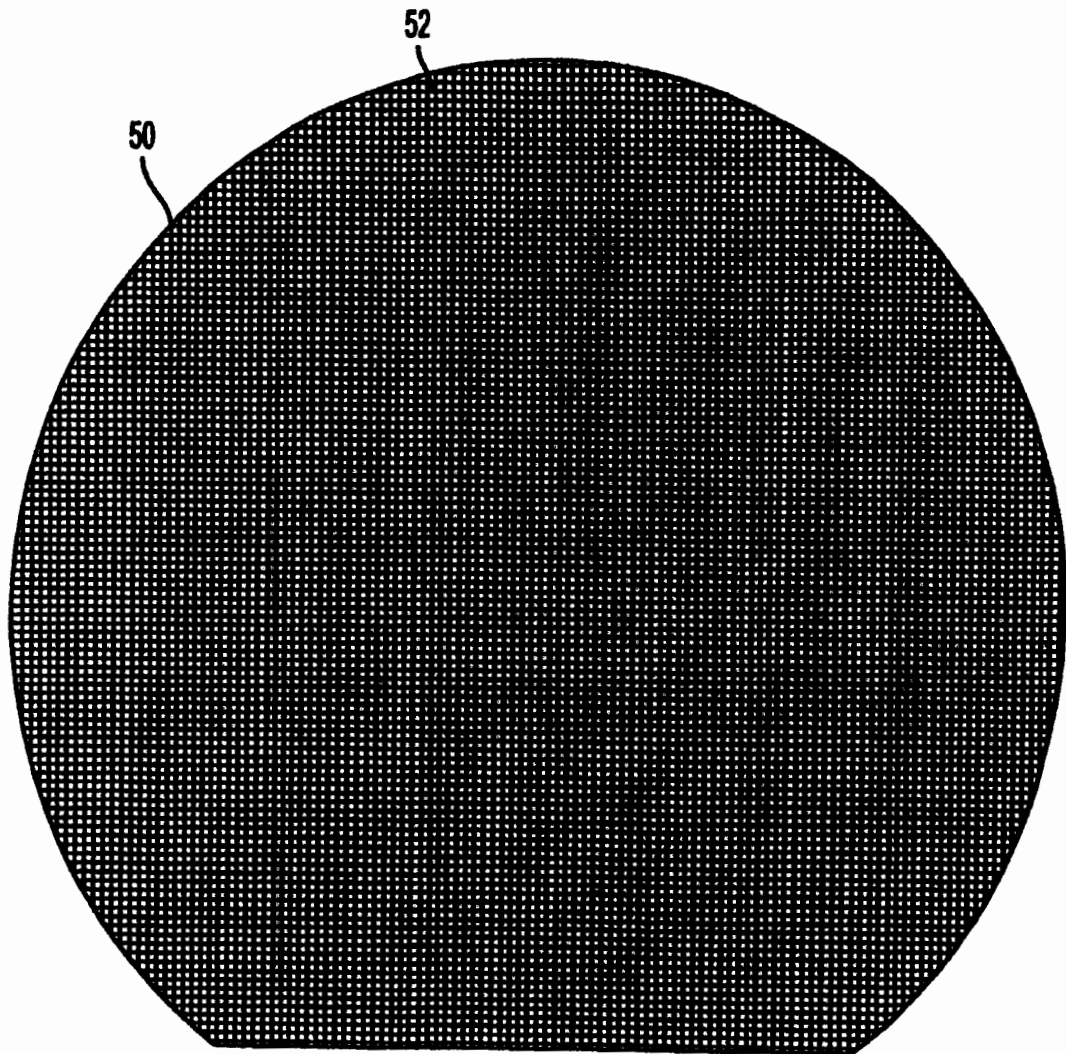


FIG. 5

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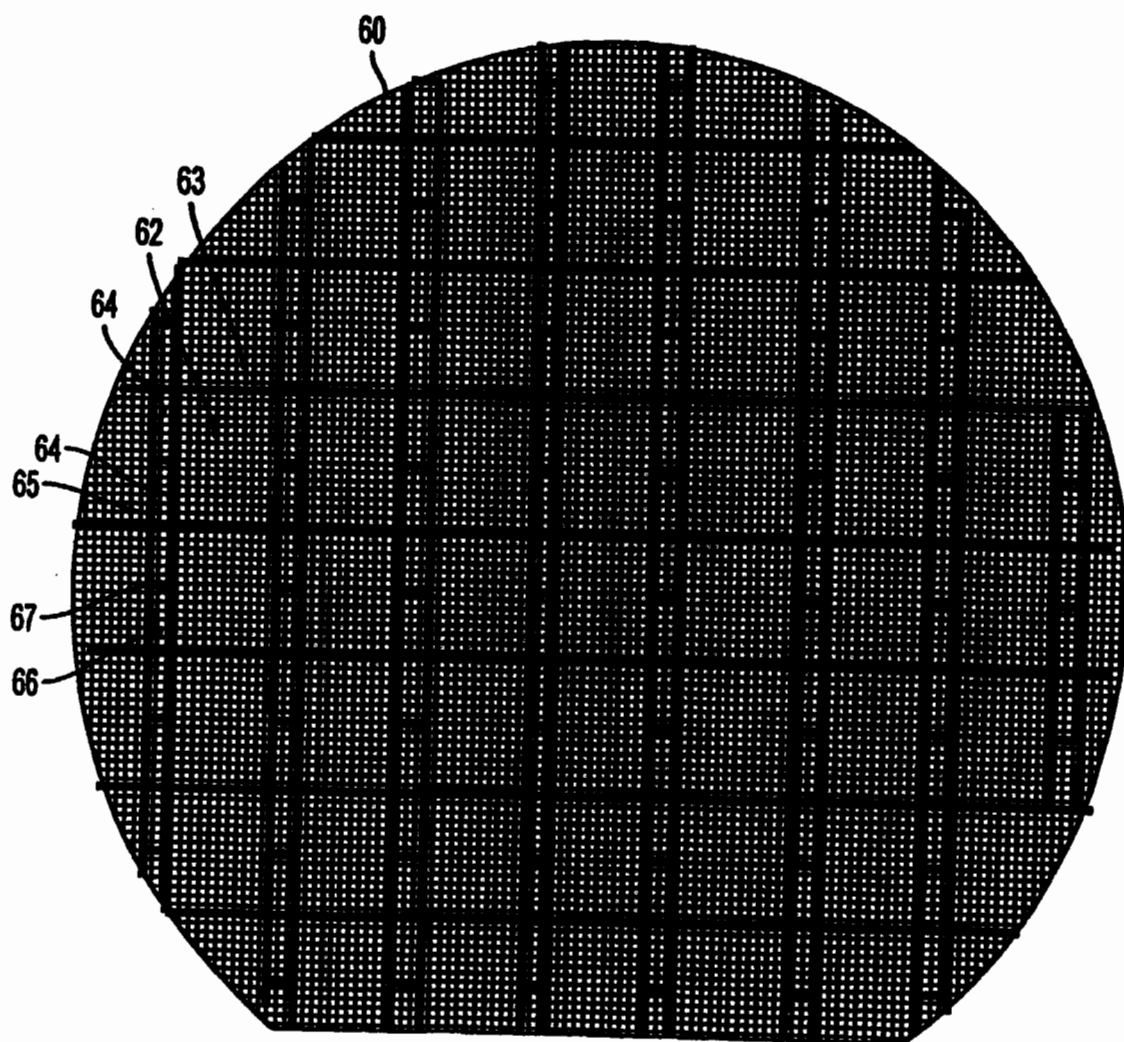


FIG. 6

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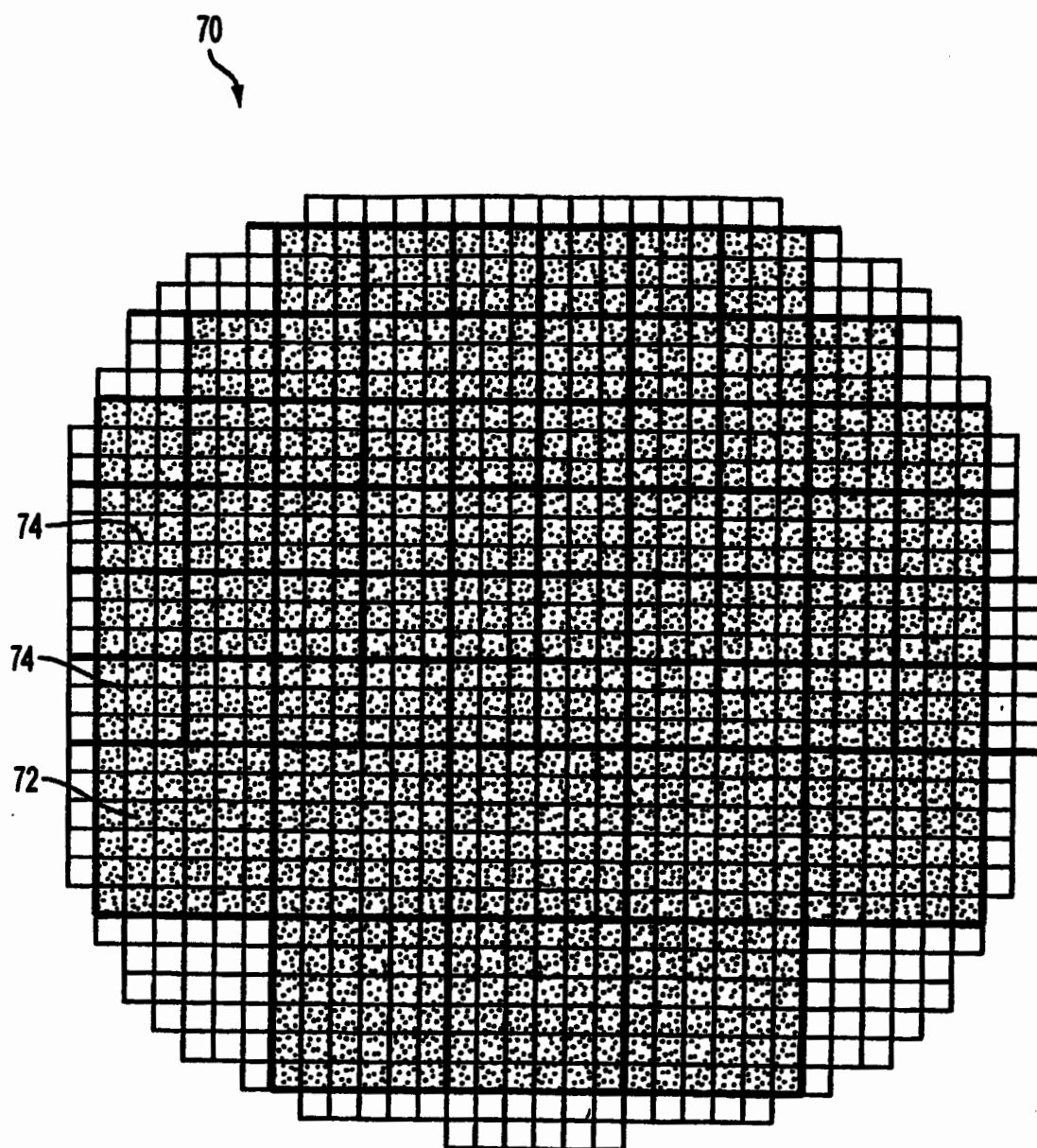


FIG. 7

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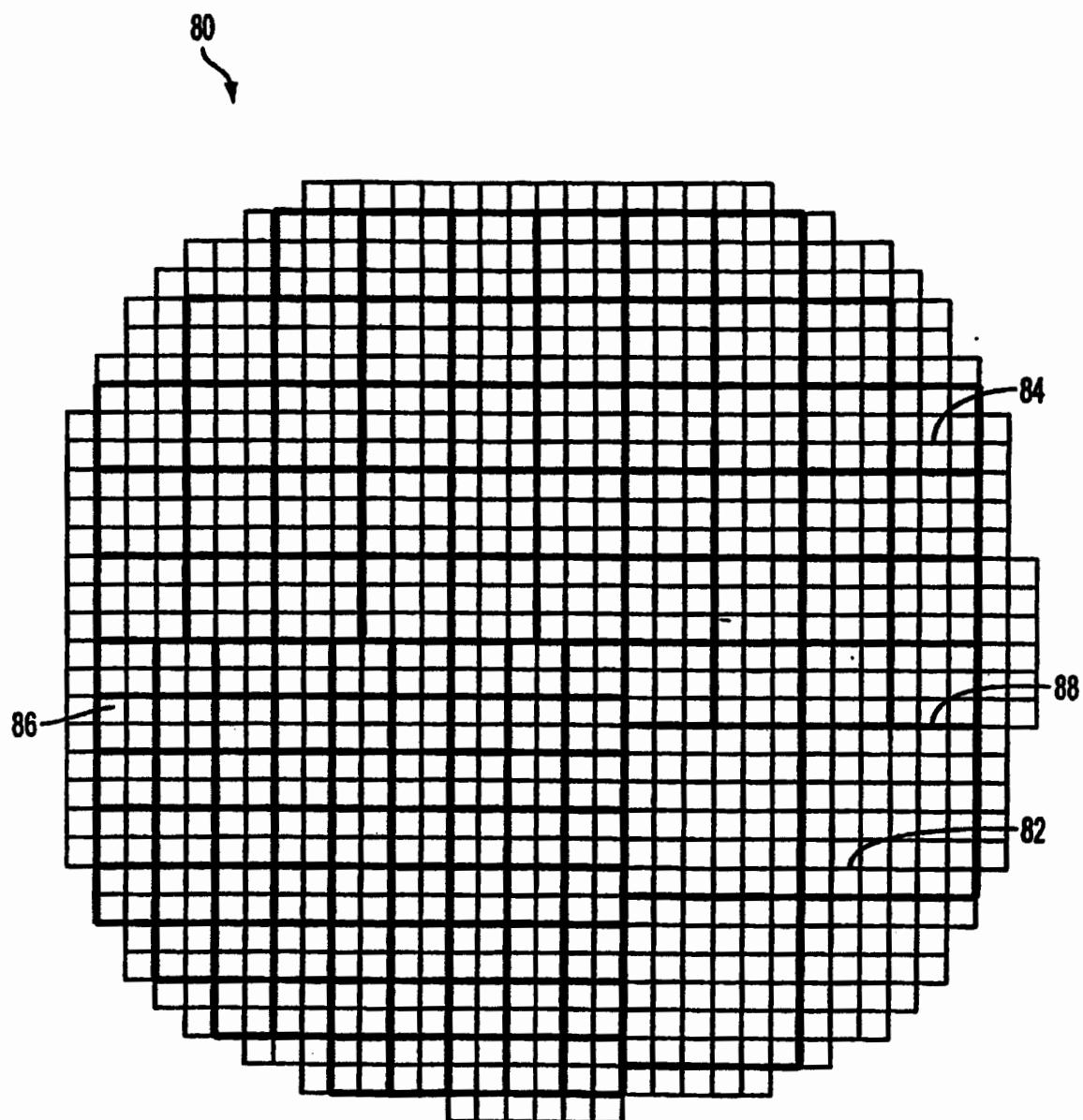
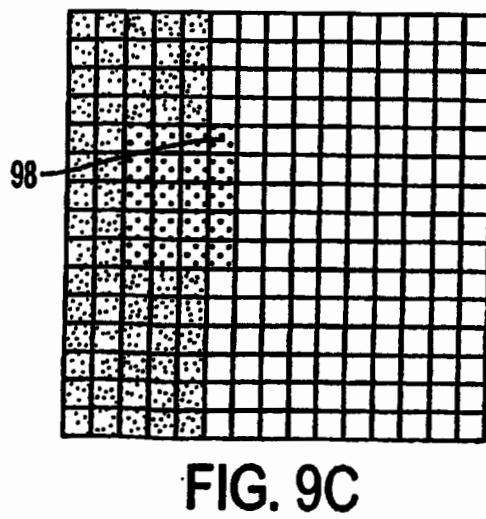
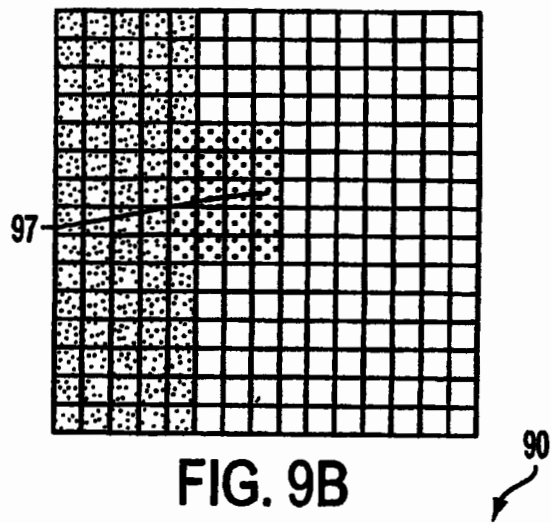
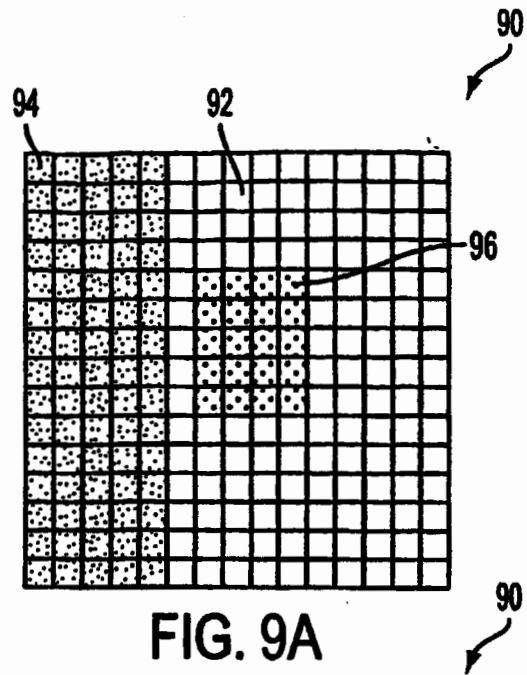


FIG. 8 .

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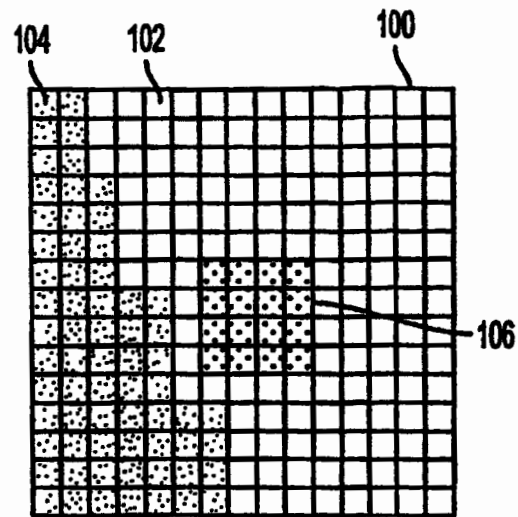


FIG. 10A

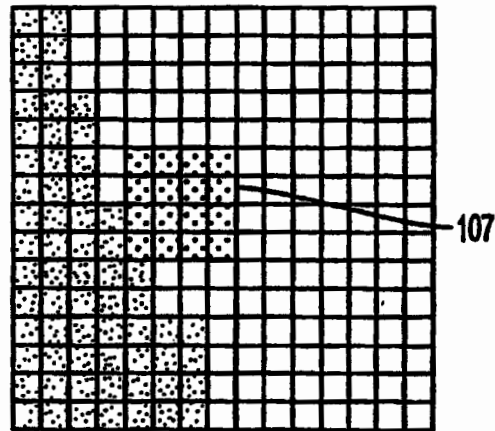


FIG. 10B

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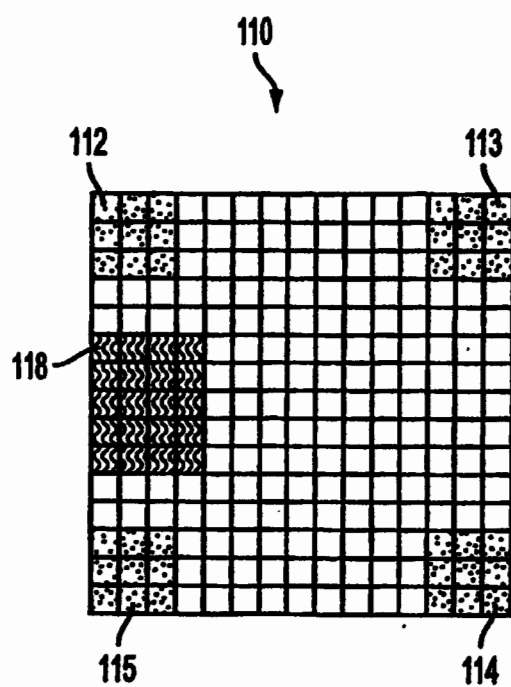


FIG. 11

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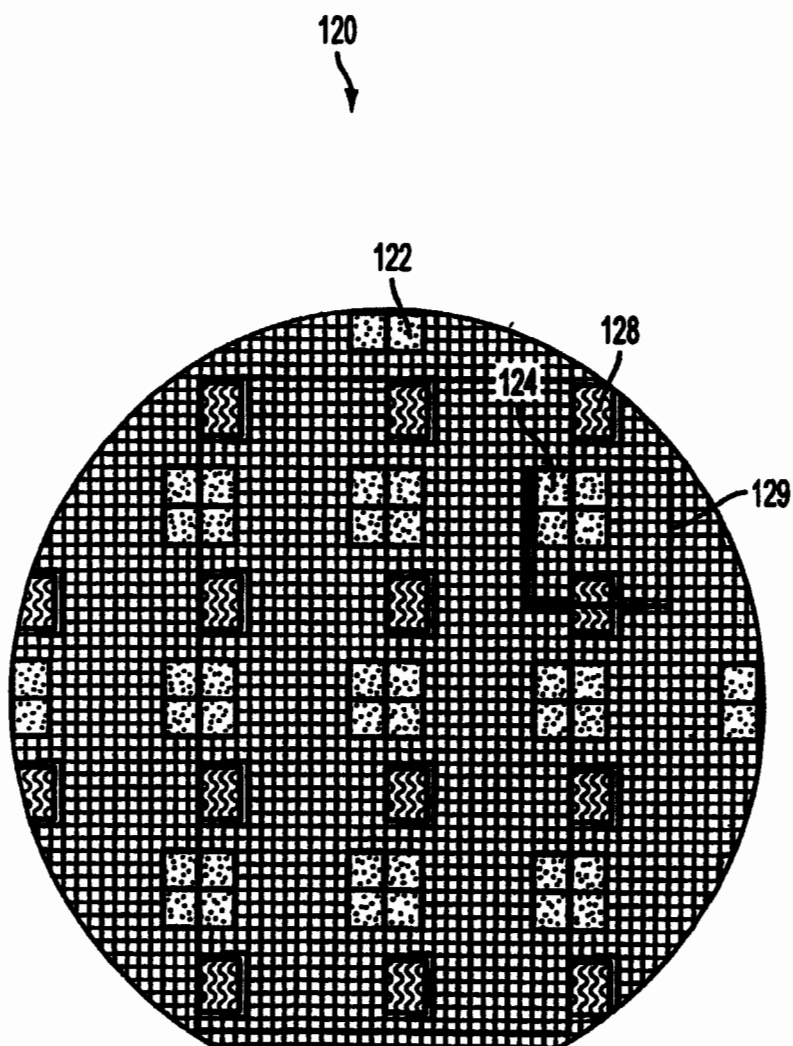


FIG. 12

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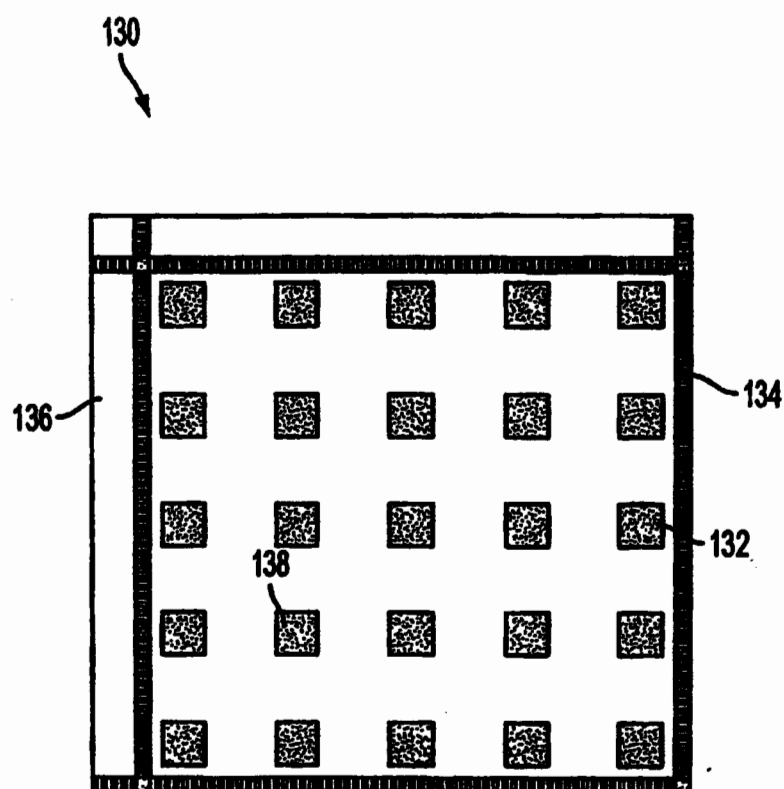


FIG. 13

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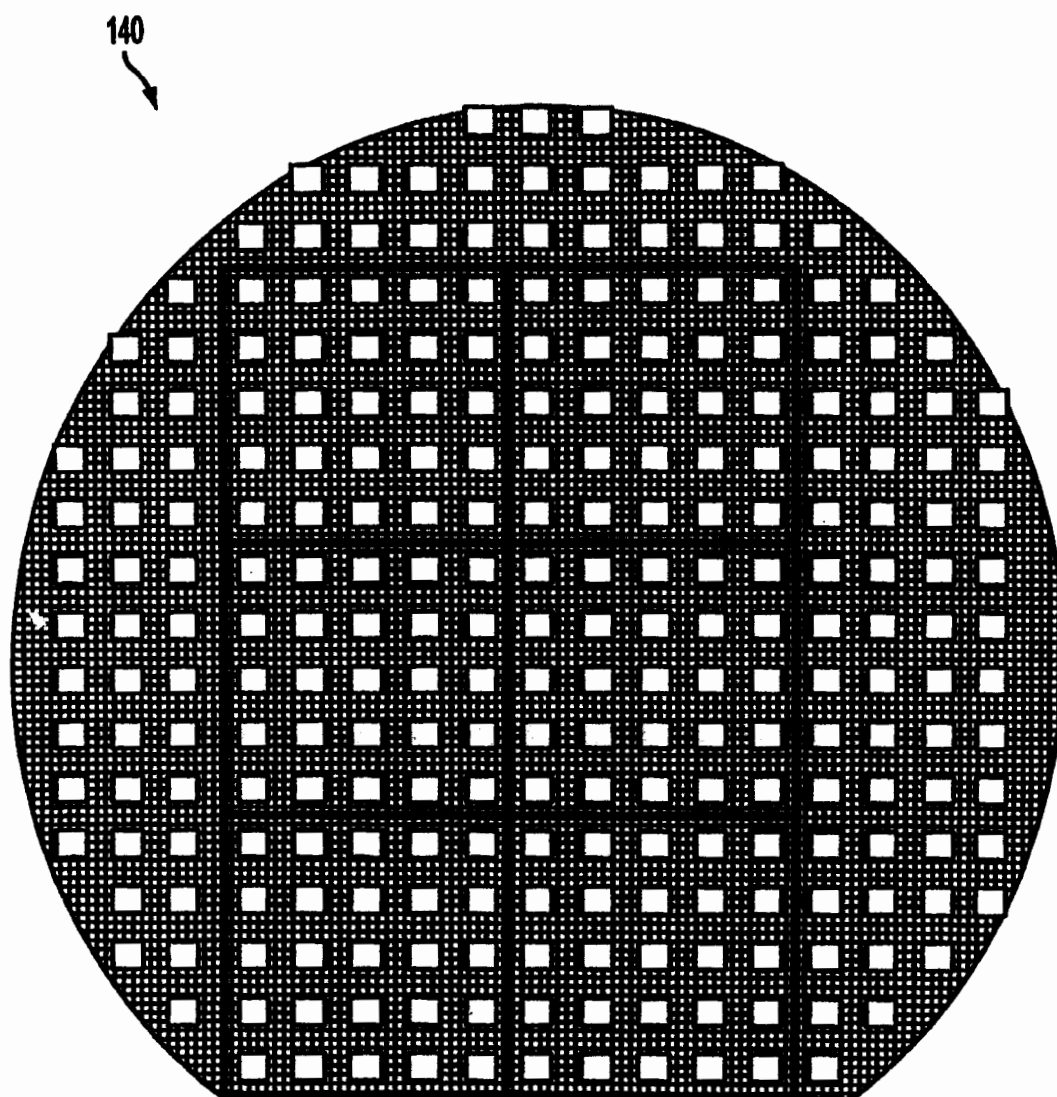
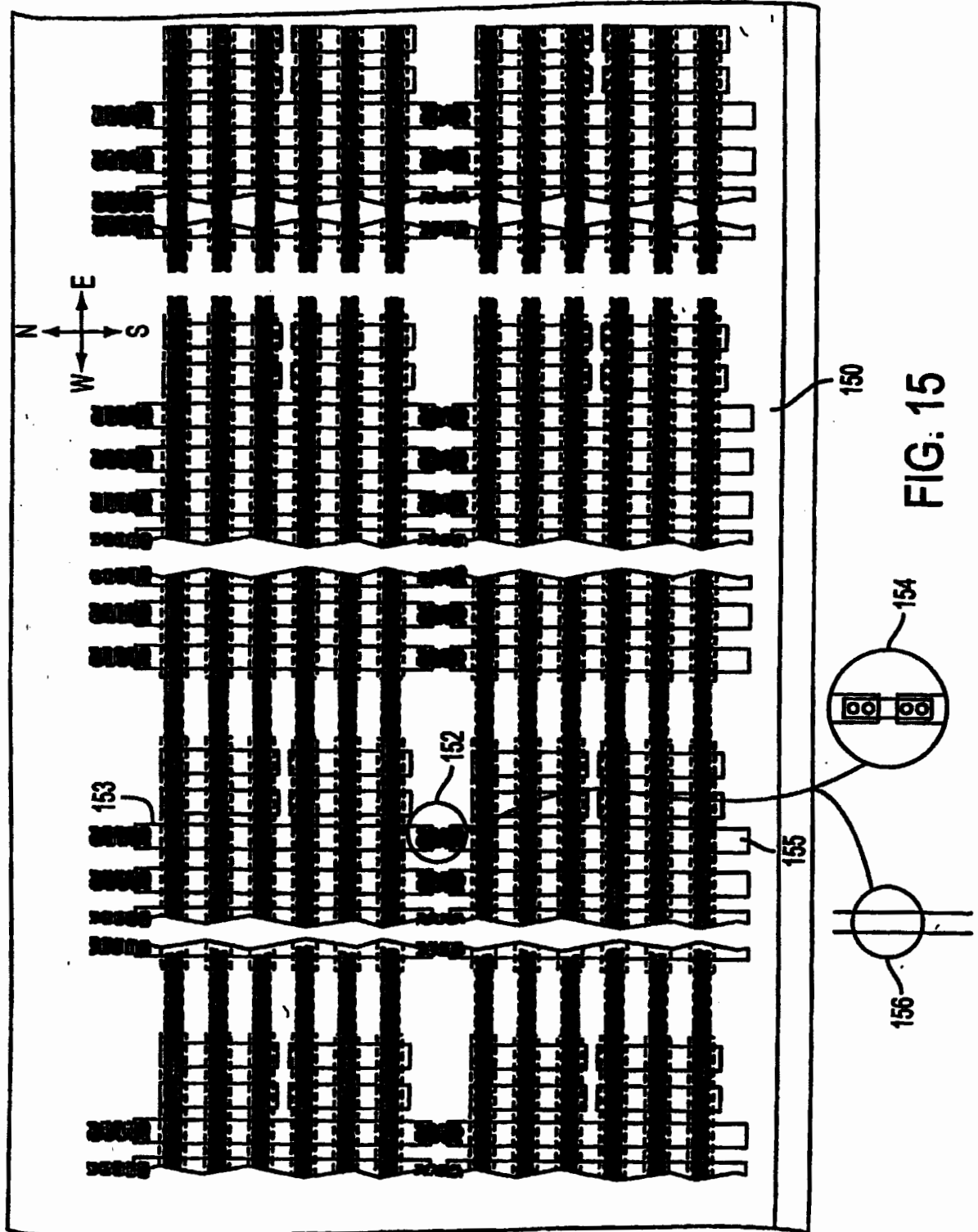


FIG. 14

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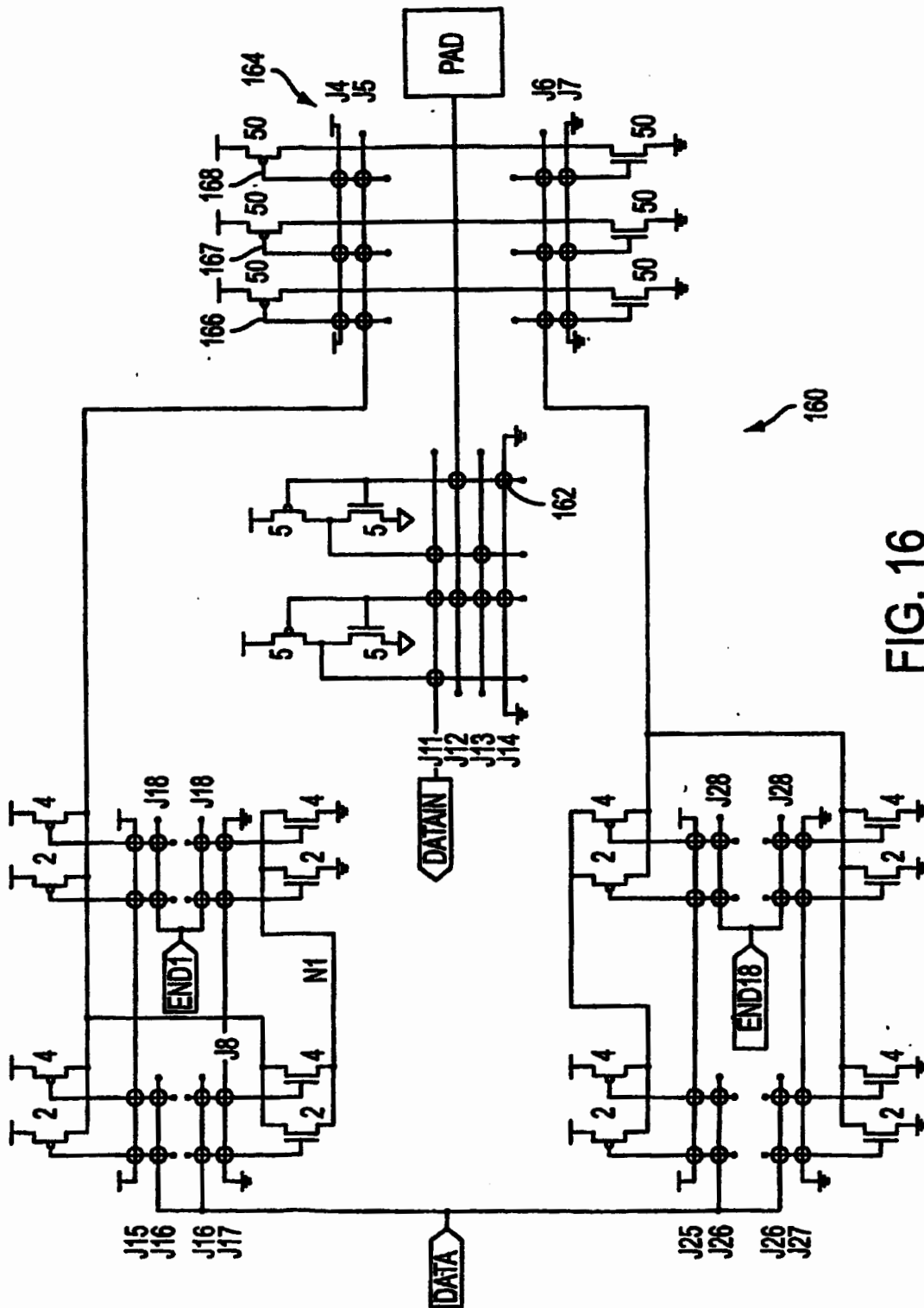


FIG. 16

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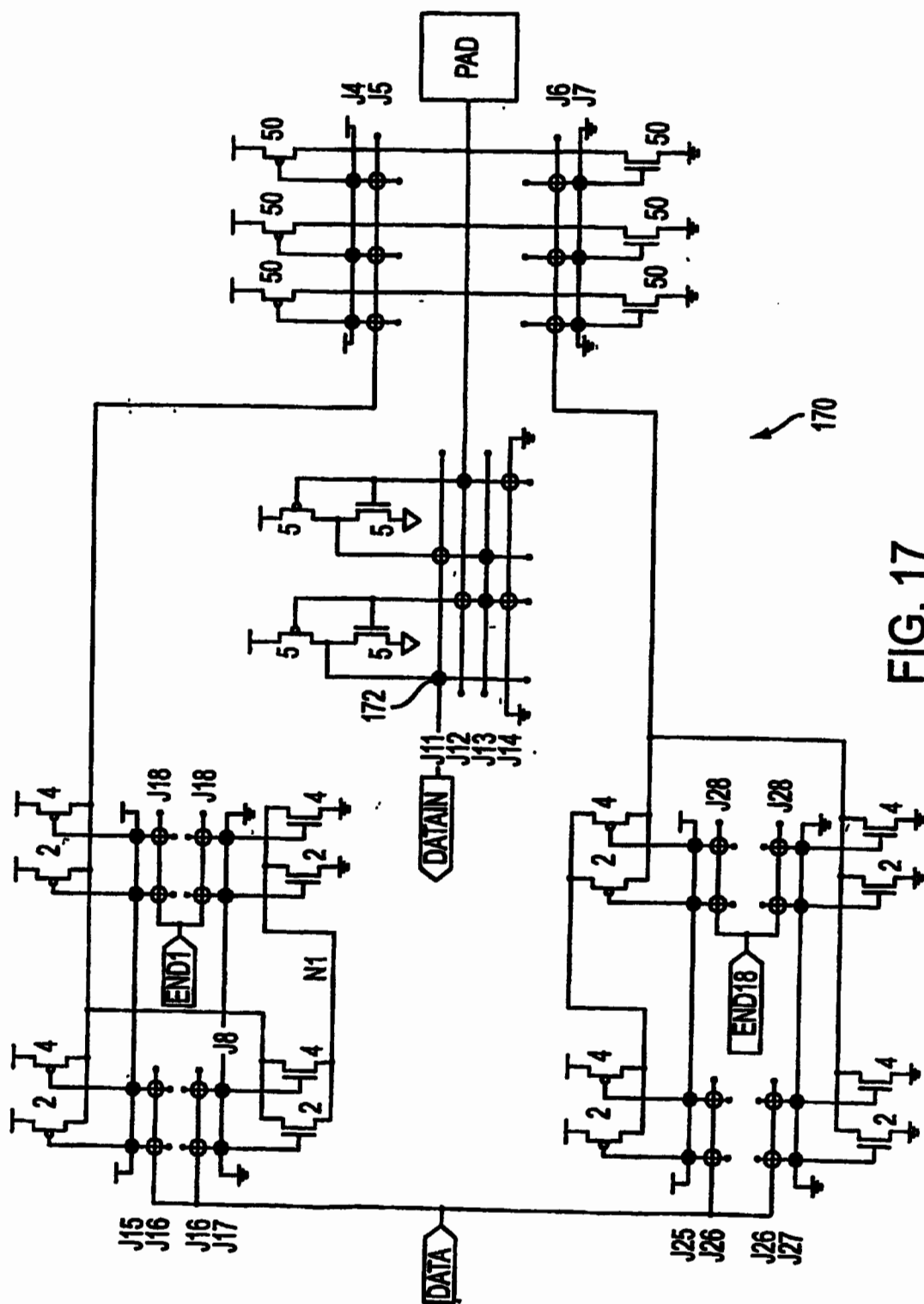


FIG. 17

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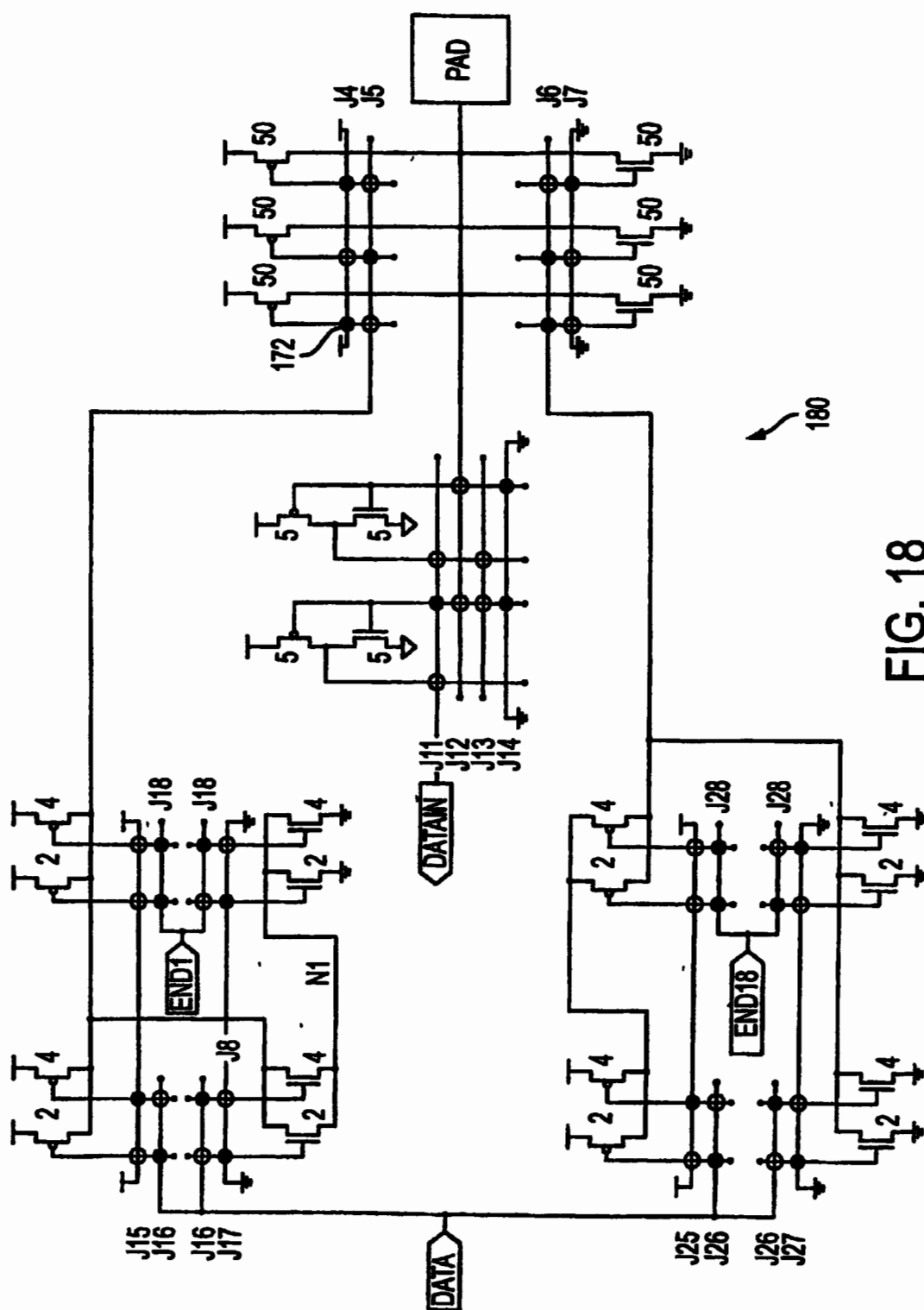


FIG. 18

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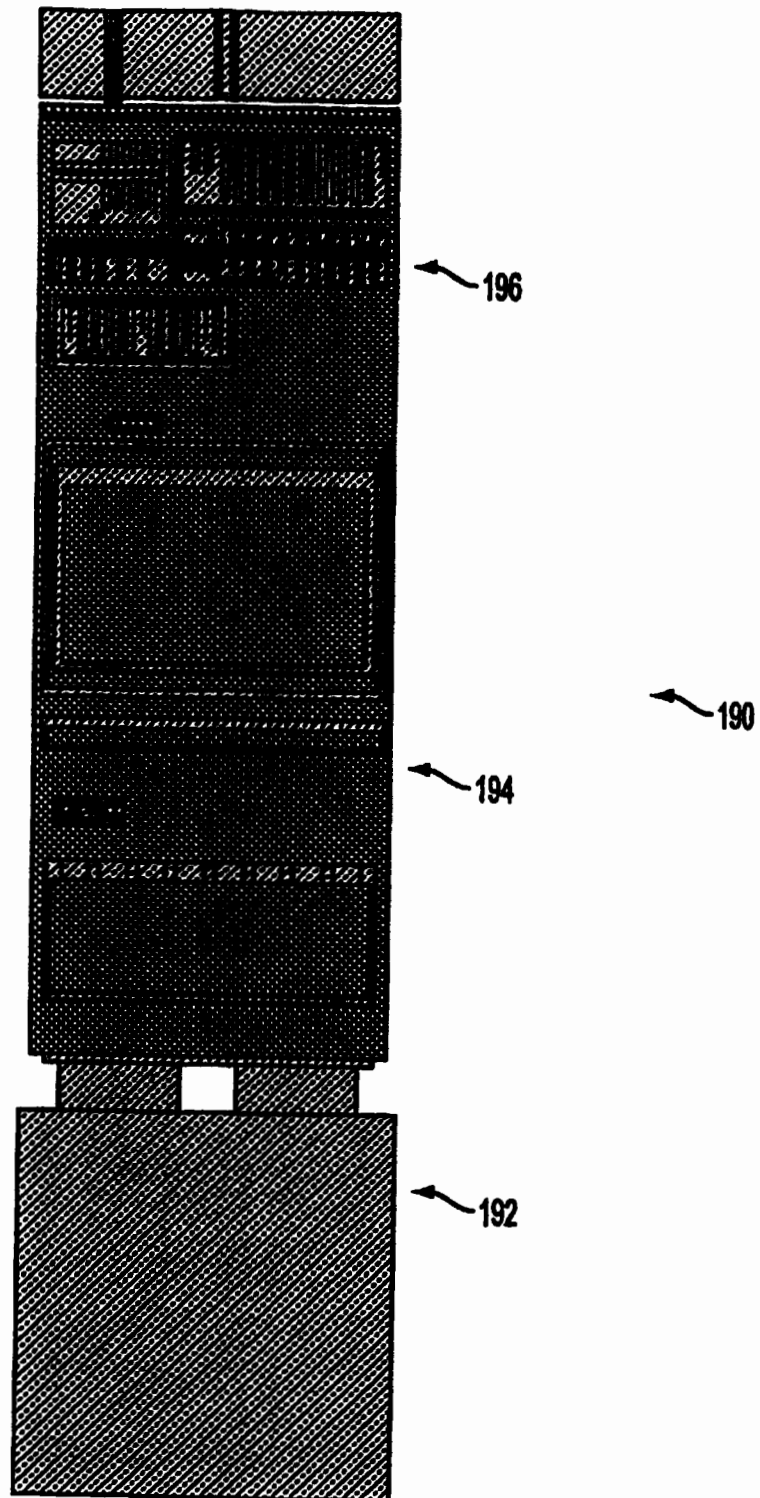


FIG. 19

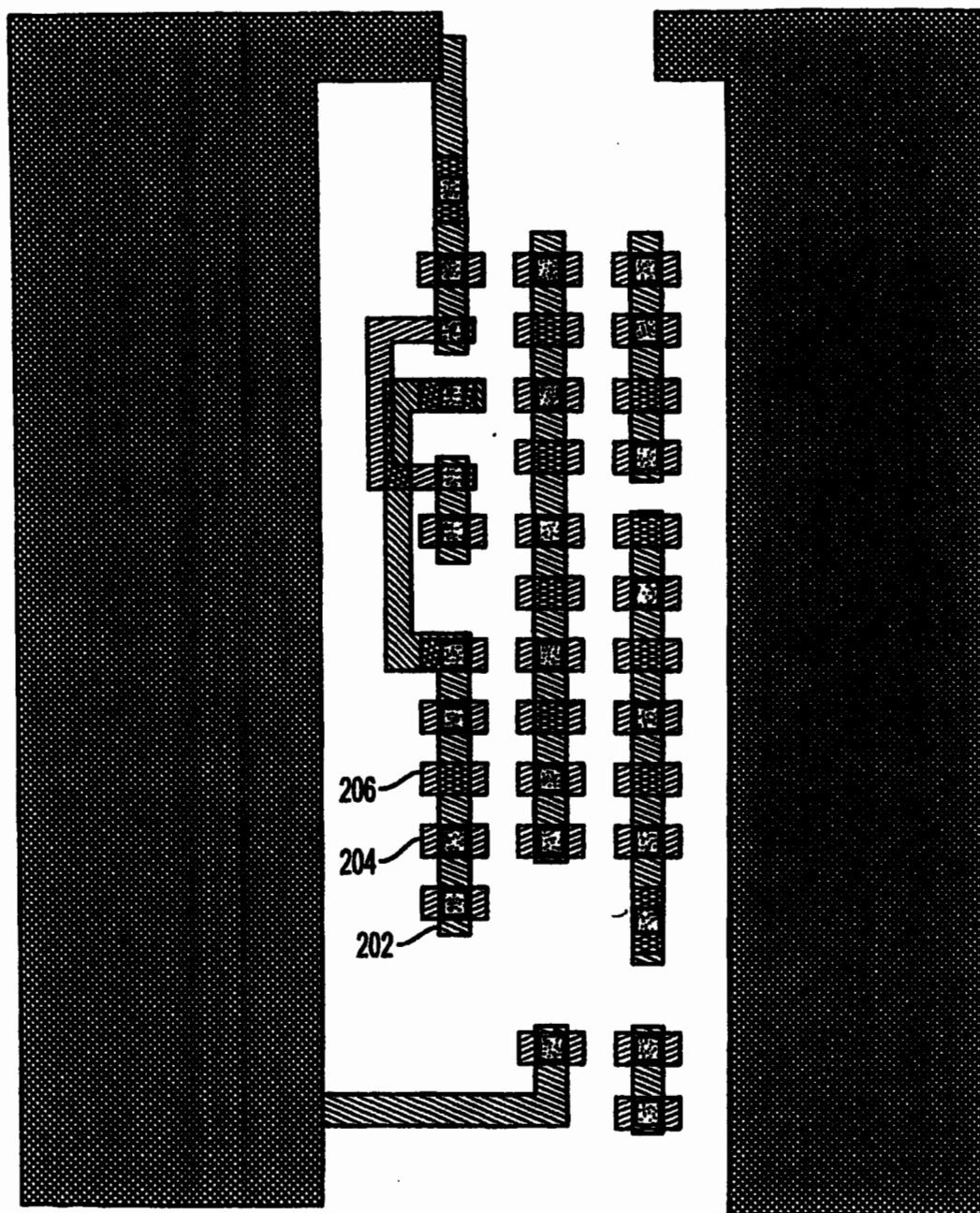
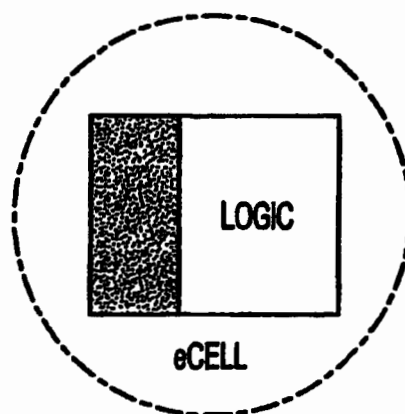
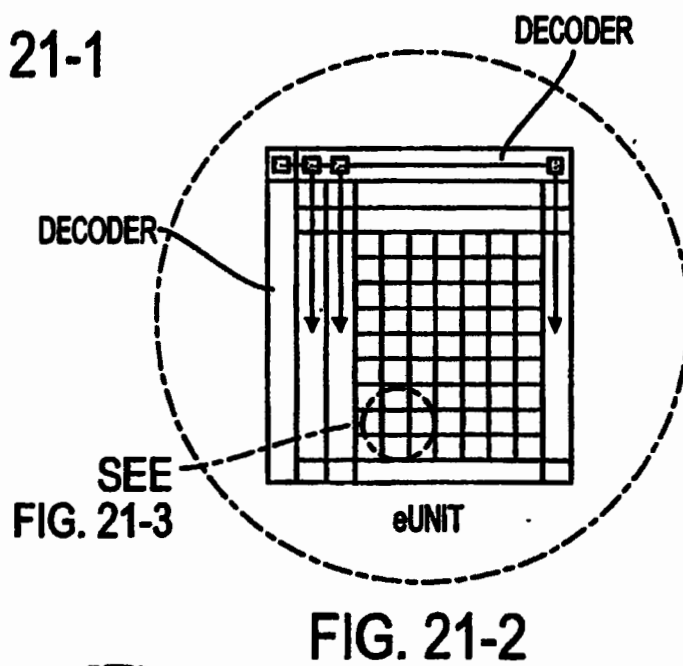
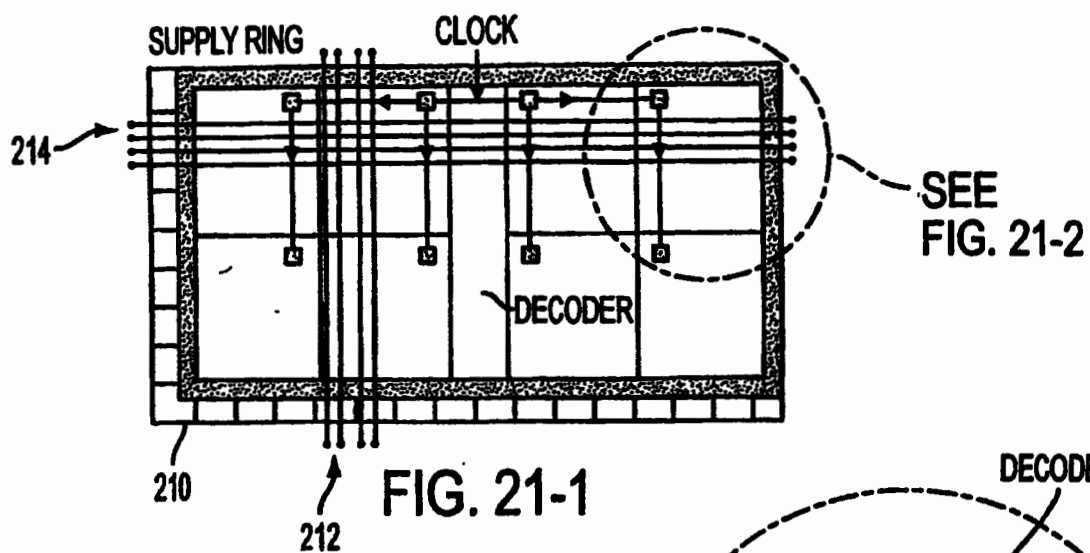


FIG. 20

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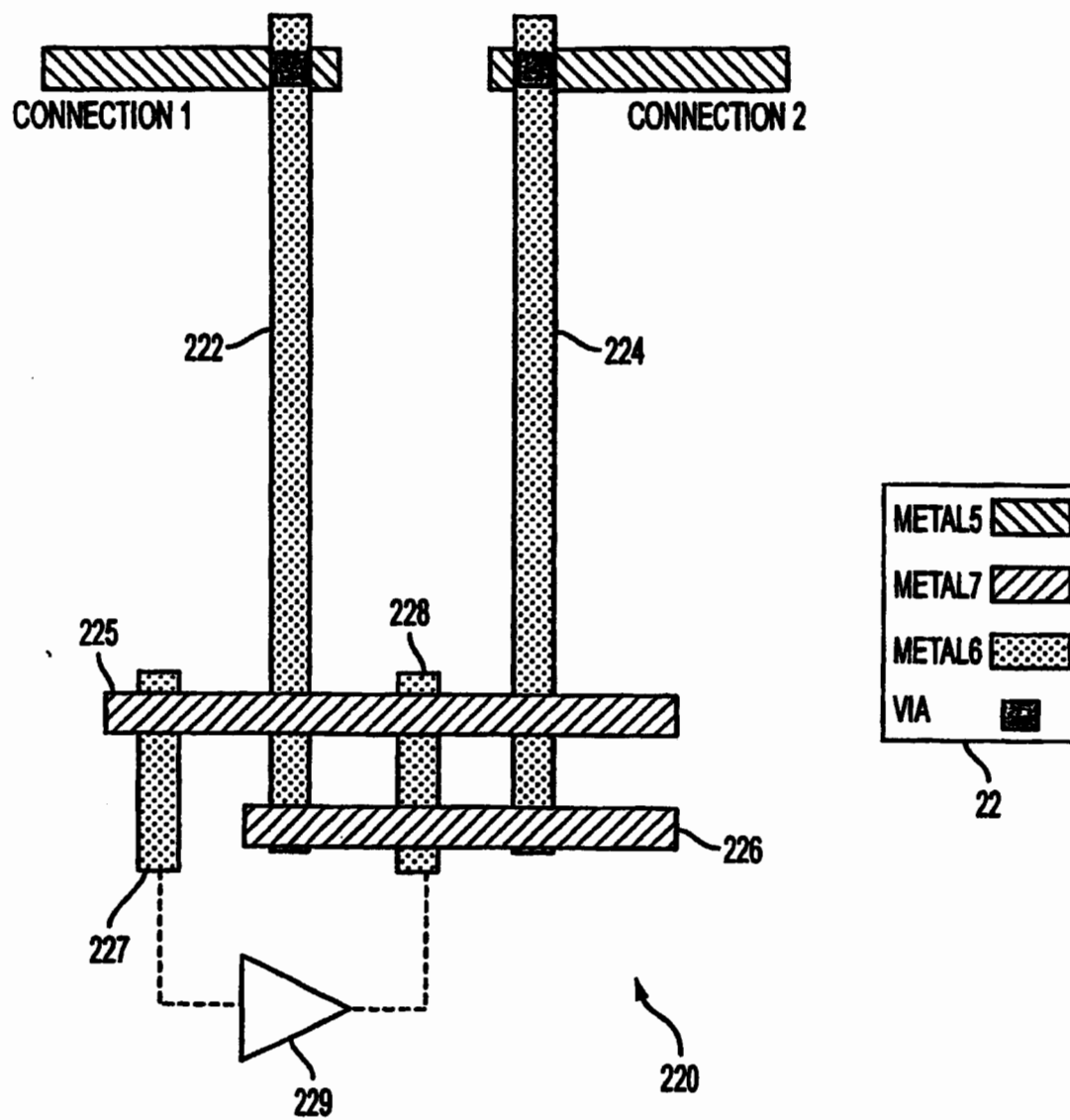


FIG. 22

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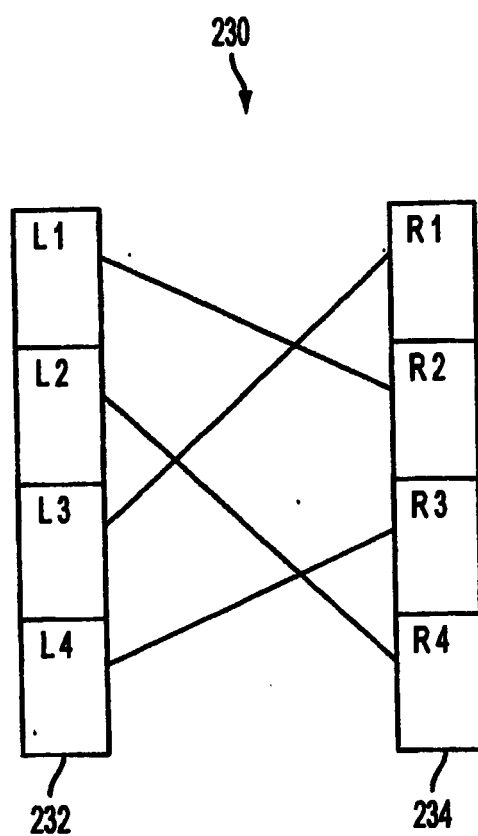


FIG. 23

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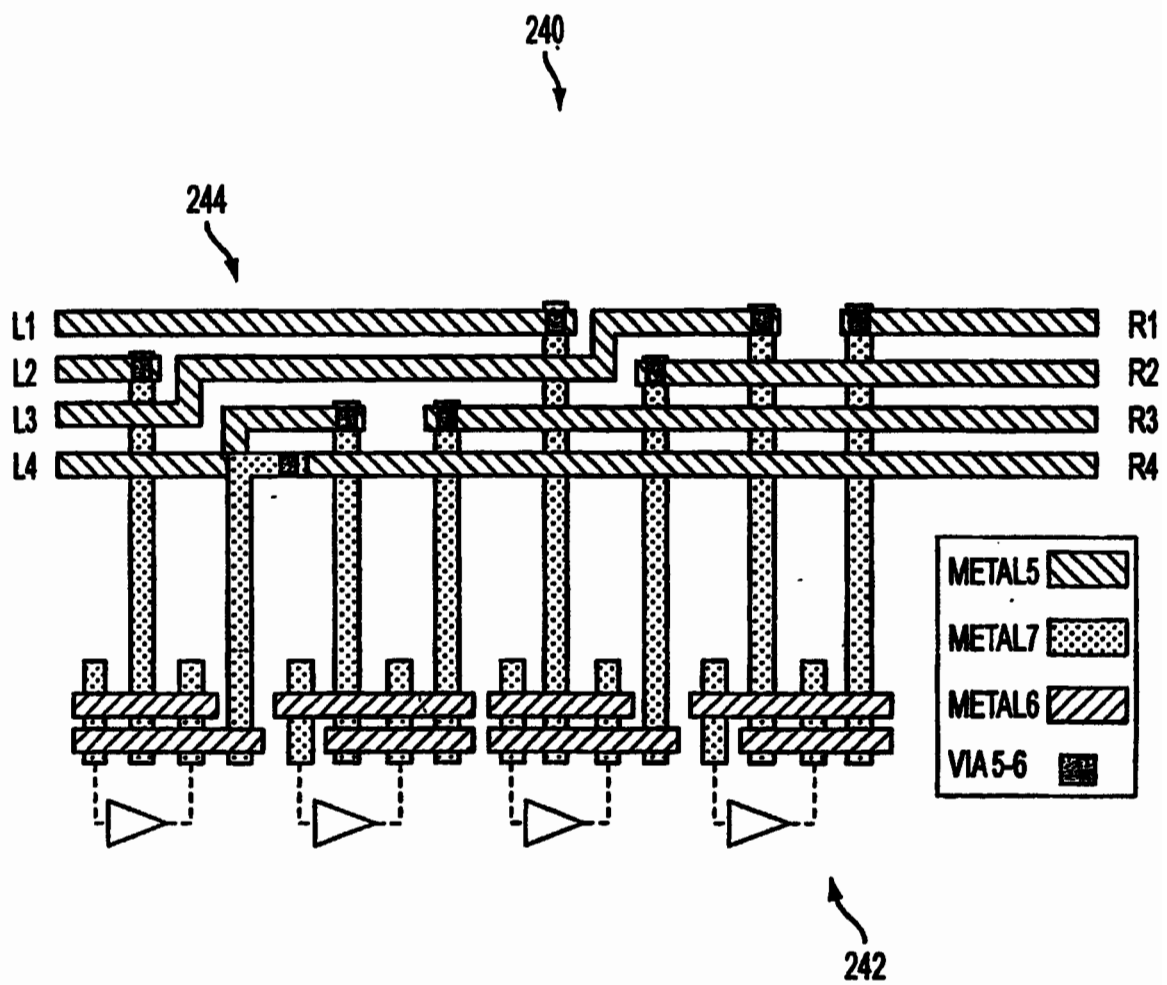


FIG. 24

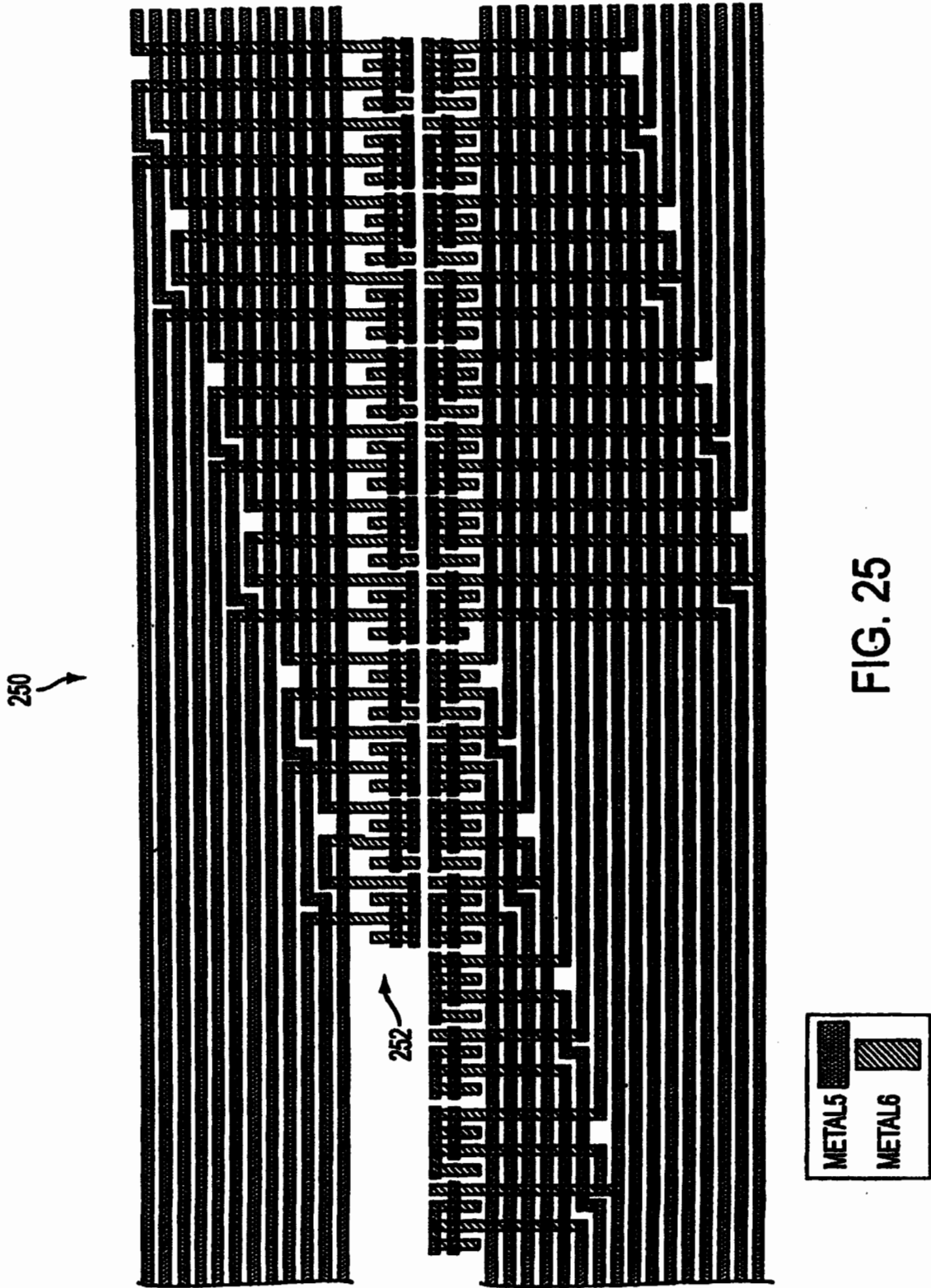


FIG. 25

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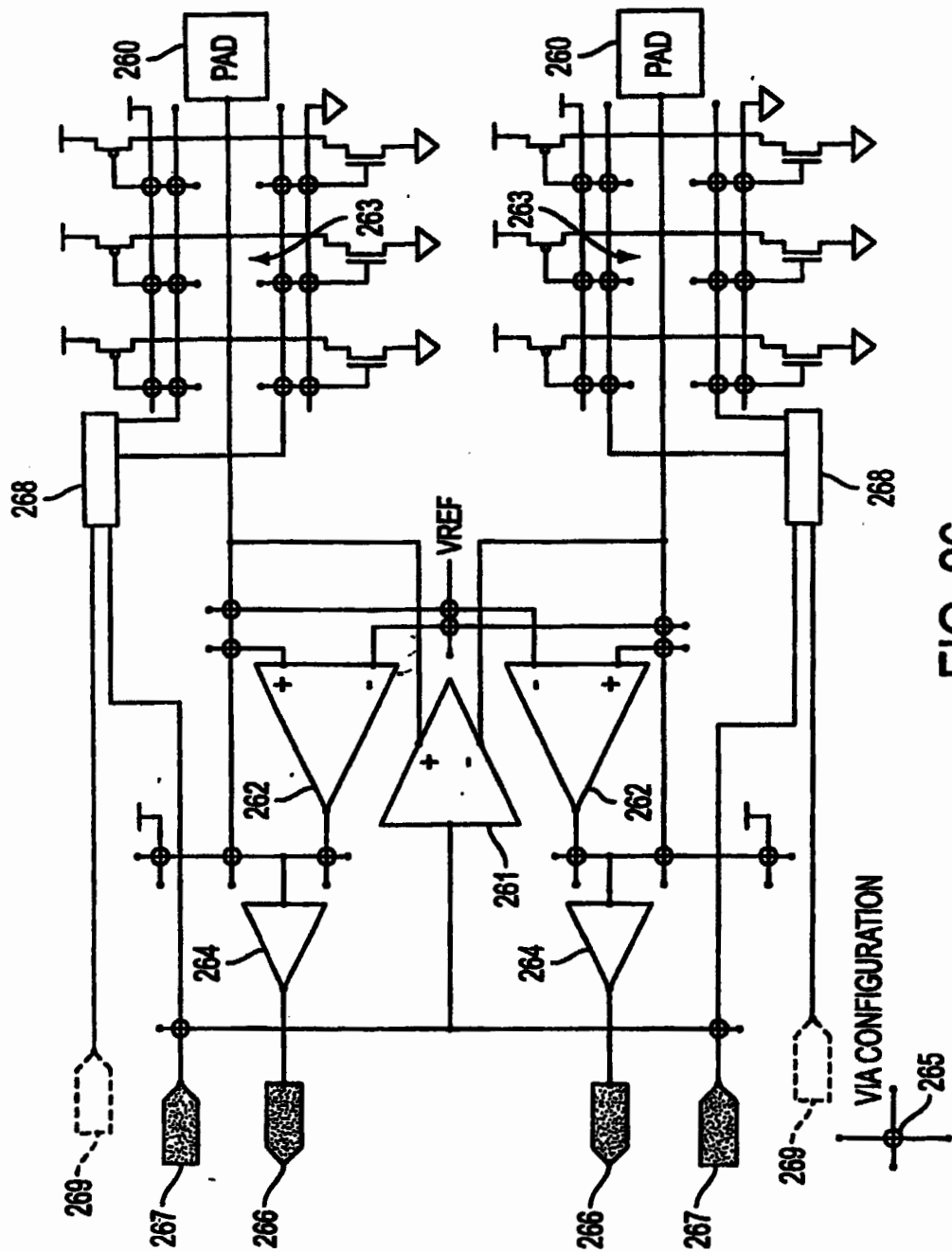


FIG. 26

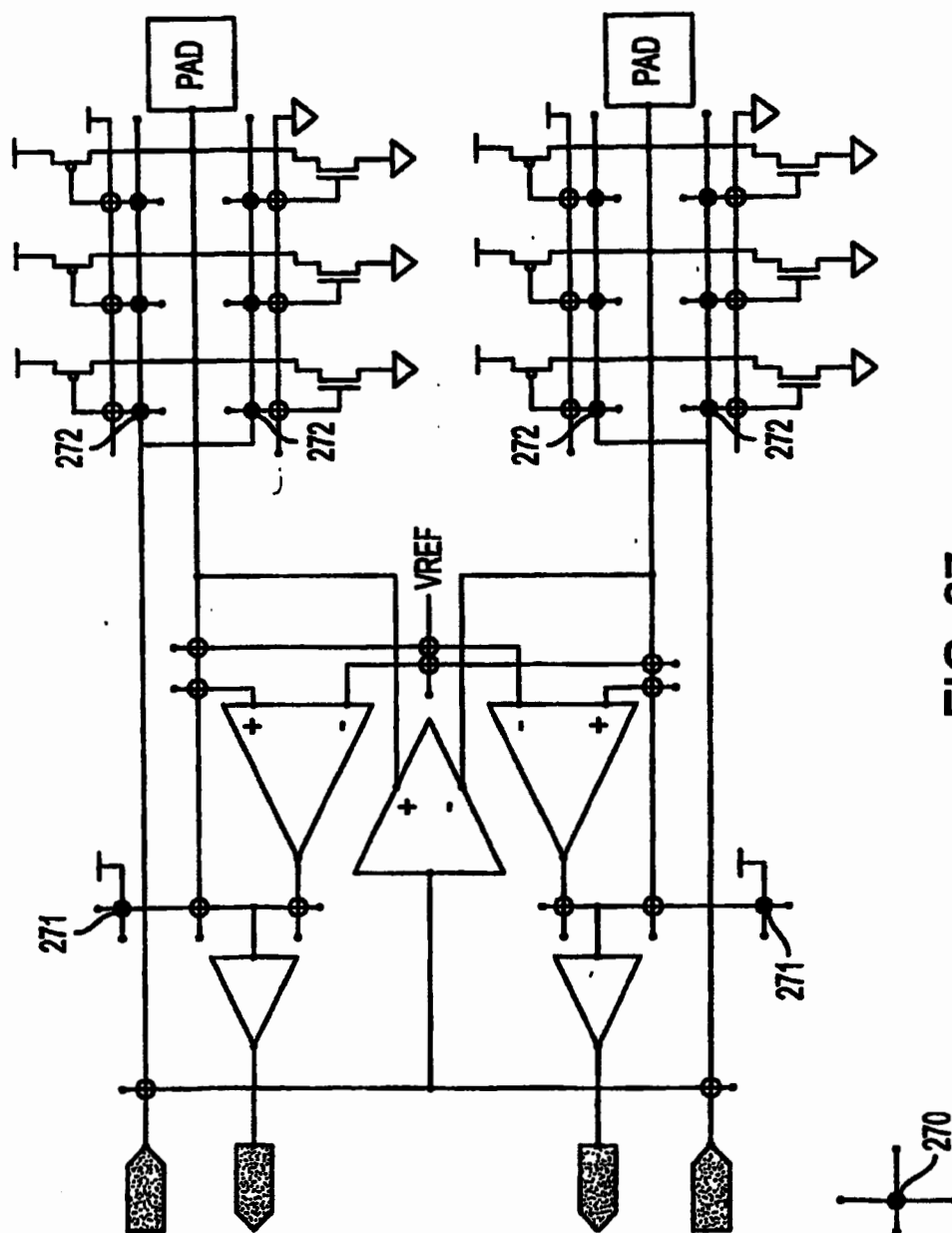


FIG. 27

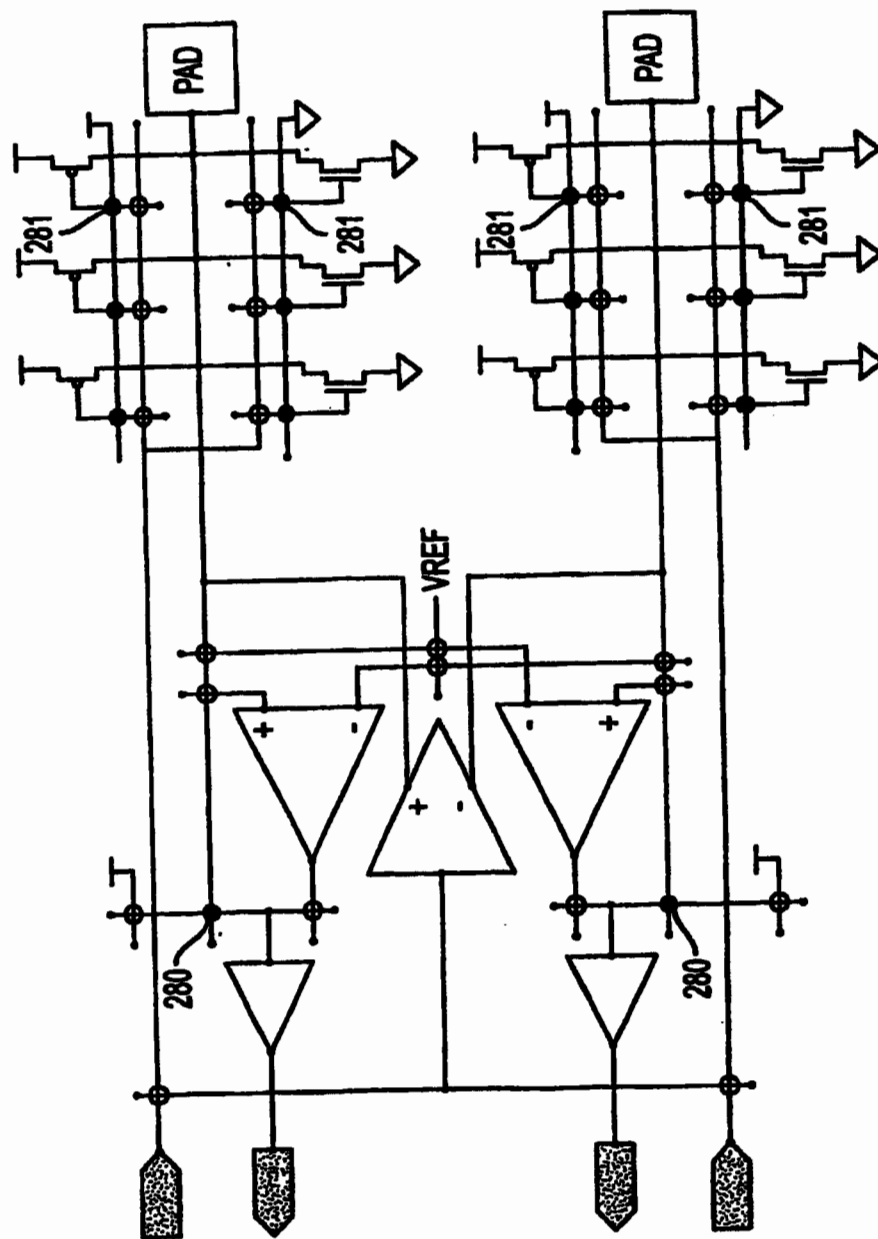


FIG. 28

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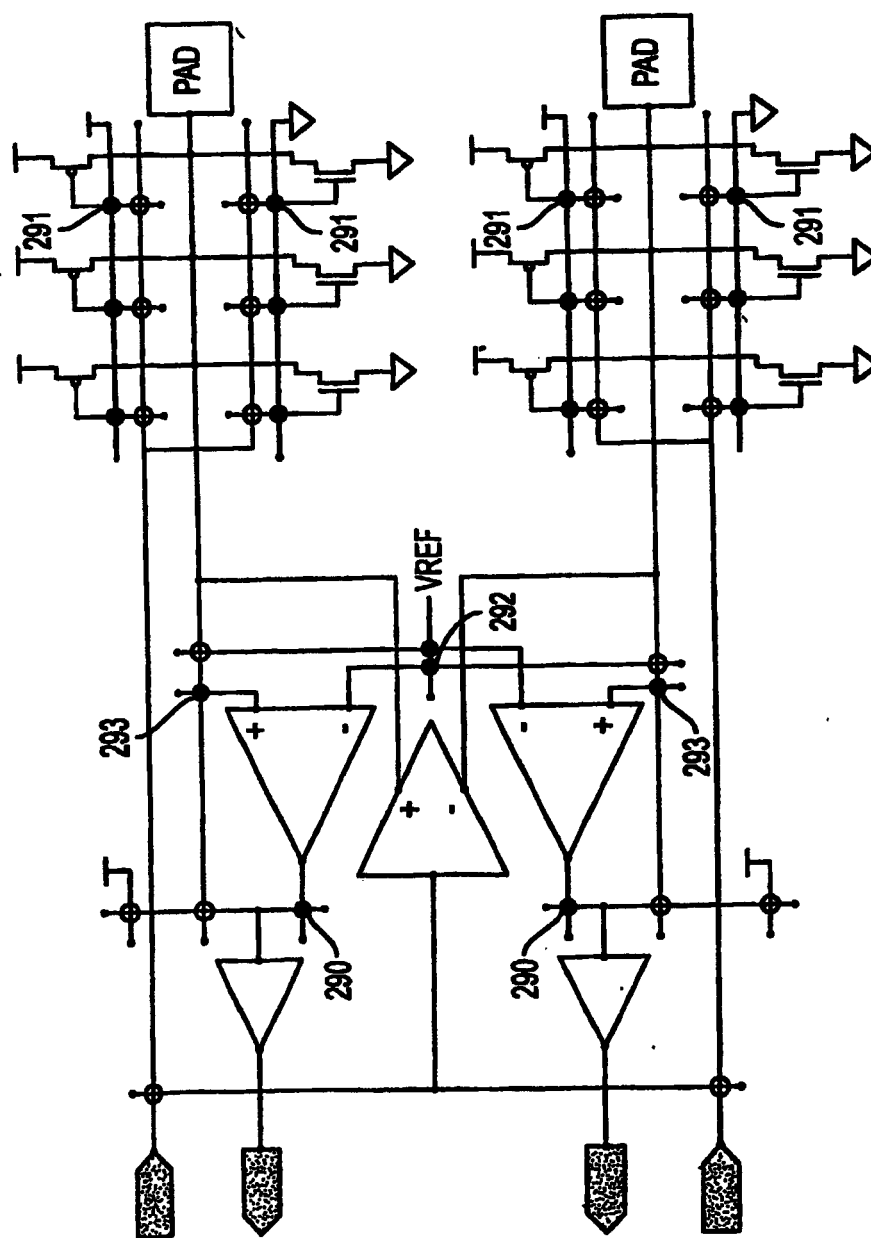


FIG. 29

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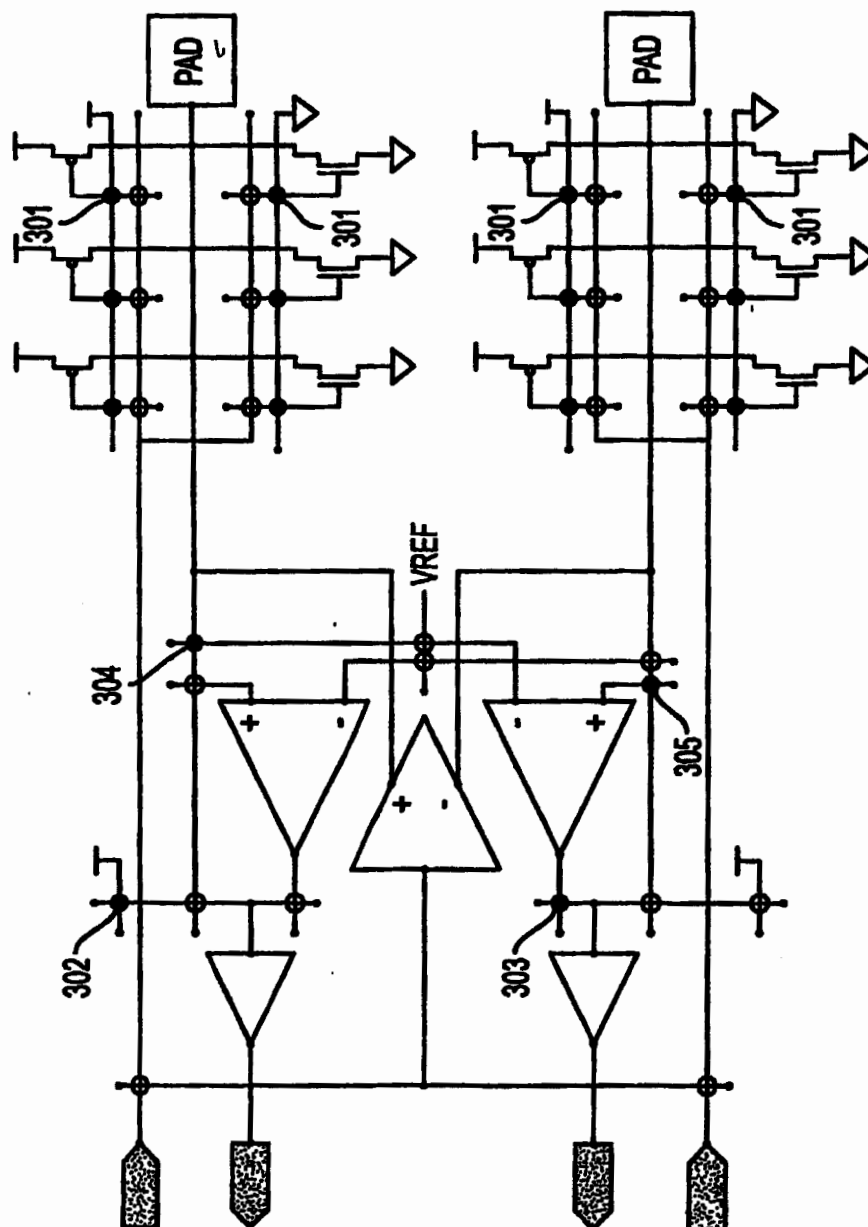


FIG. 30

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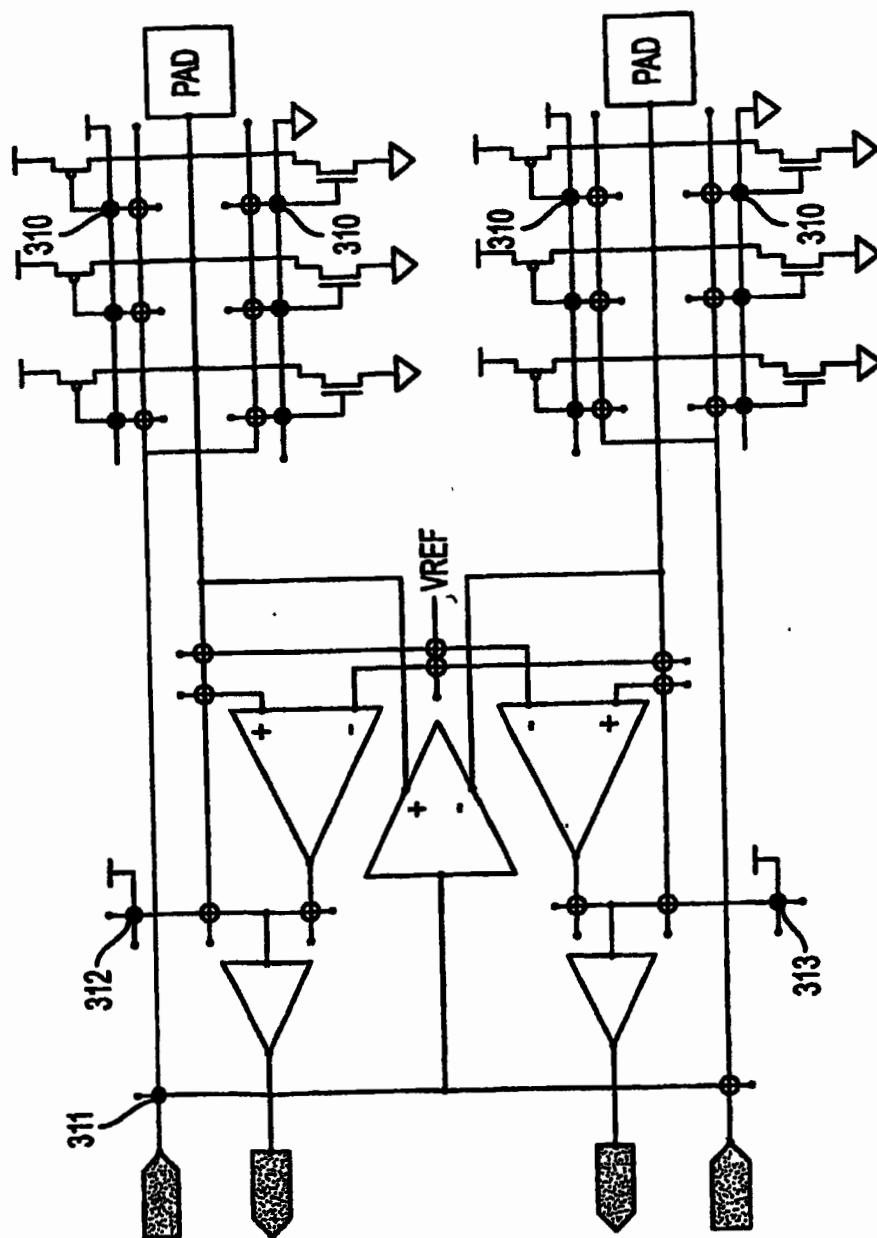


FIG. 31

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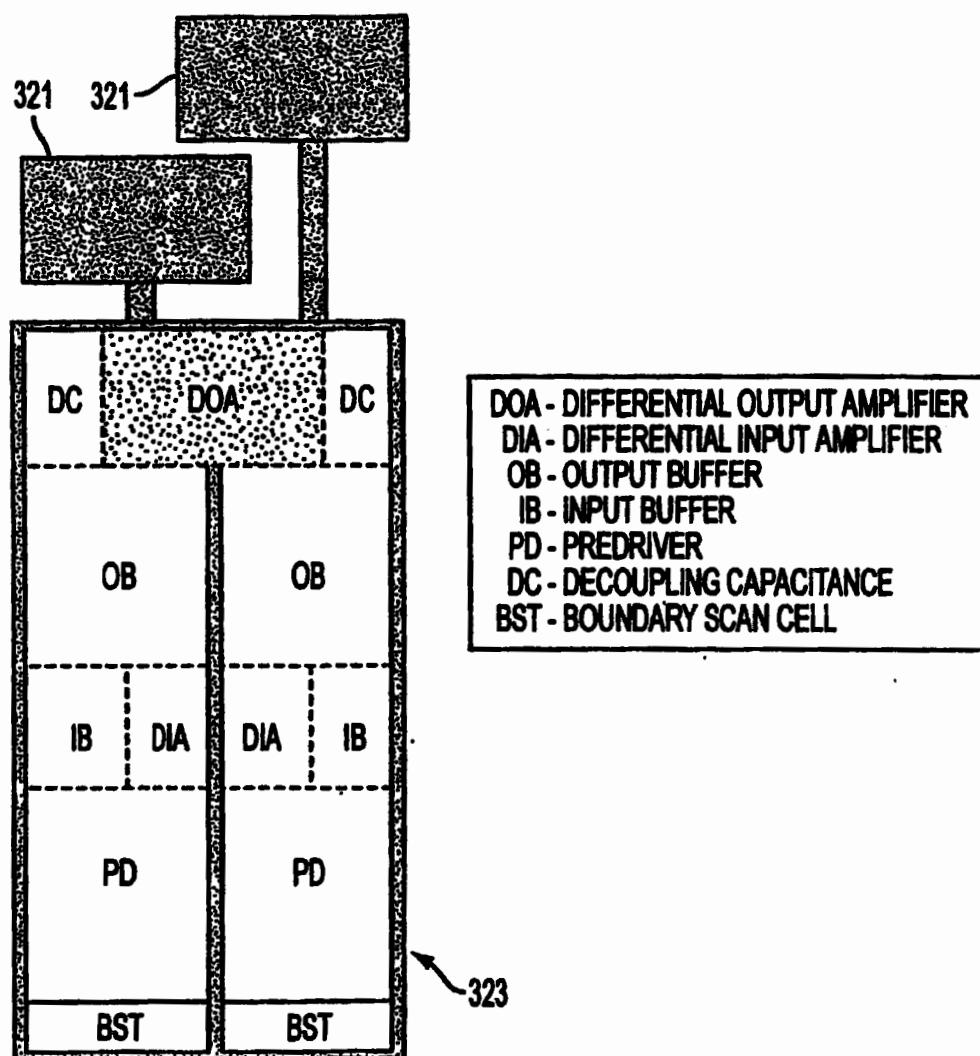


FIG. 32

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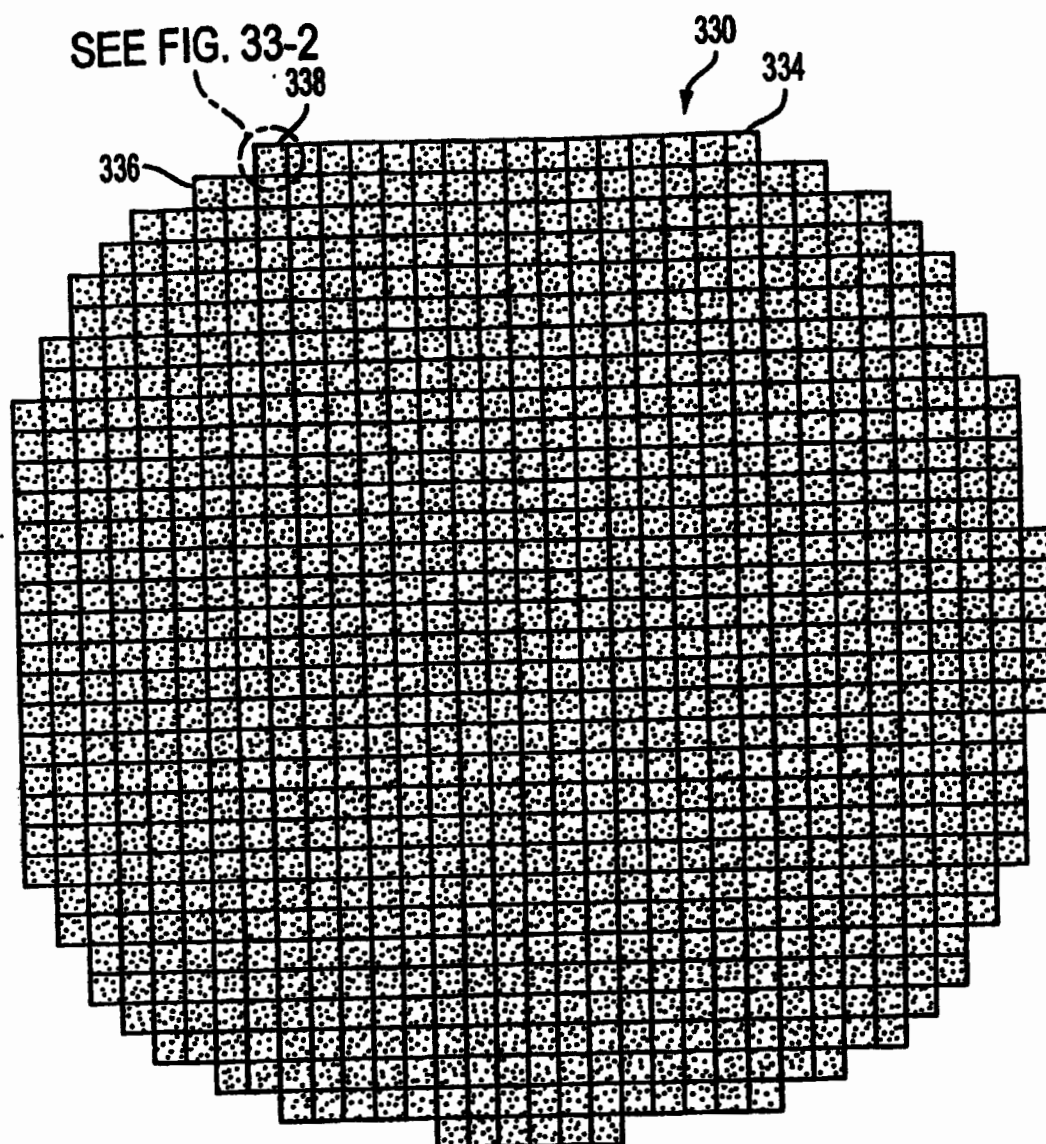


FIG. 33-1

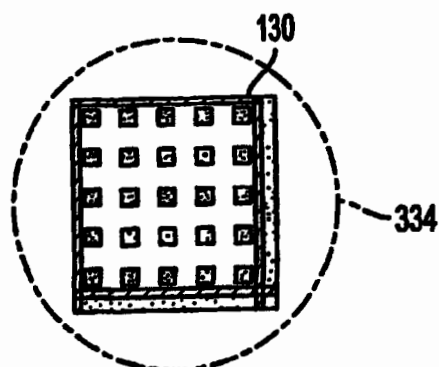


FIG. 33-2

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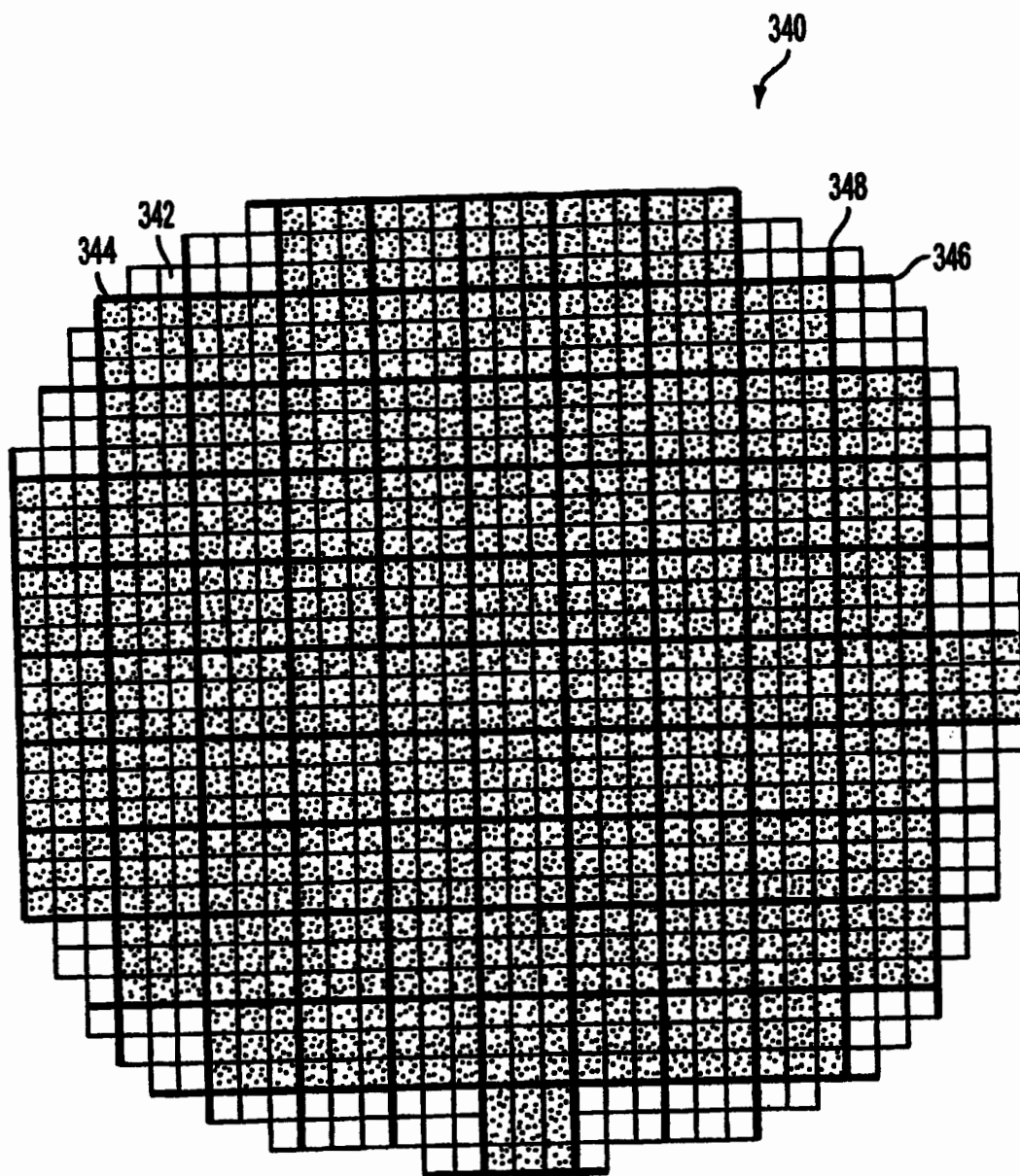


FIG. 34

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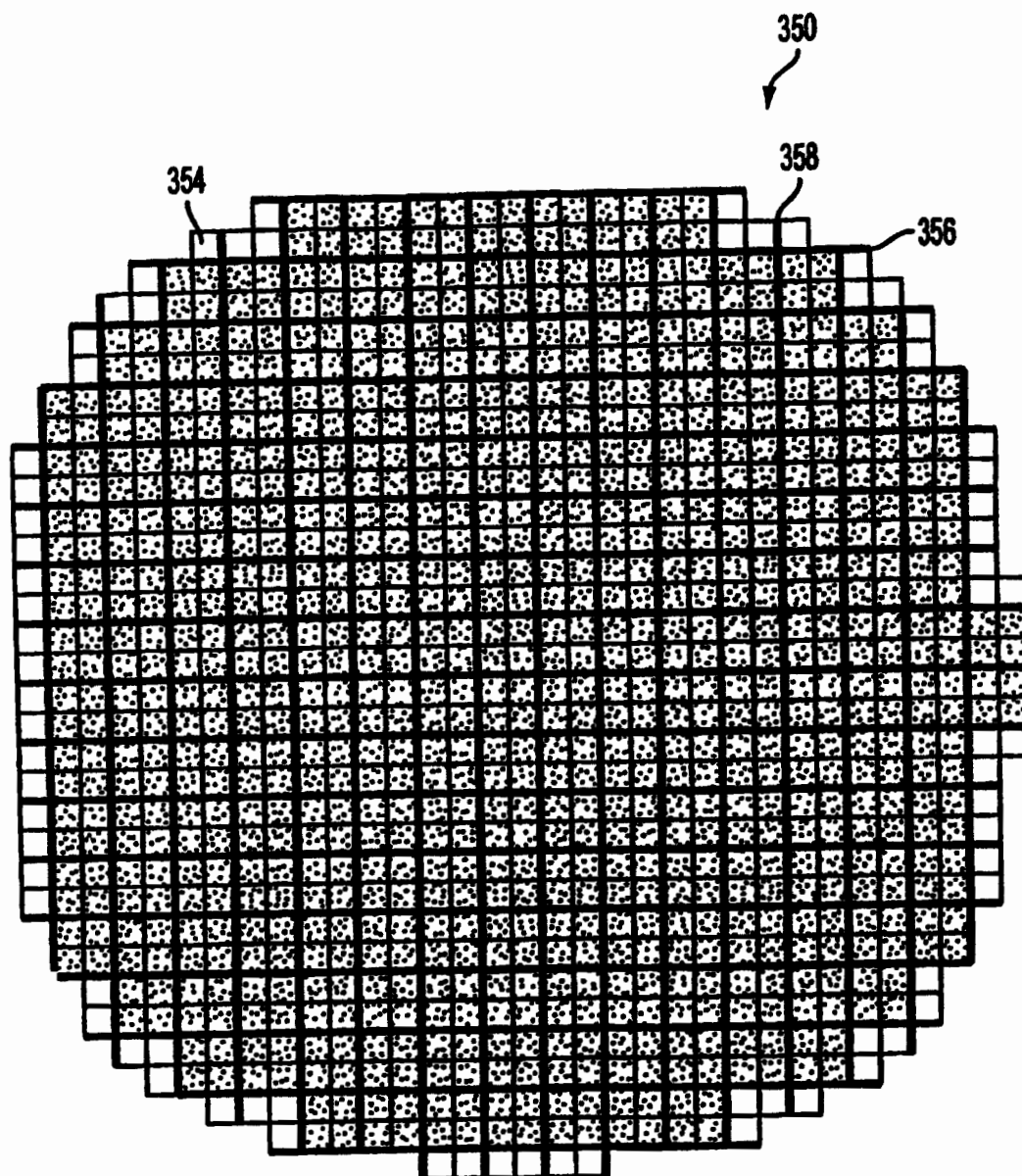


FIG. 35

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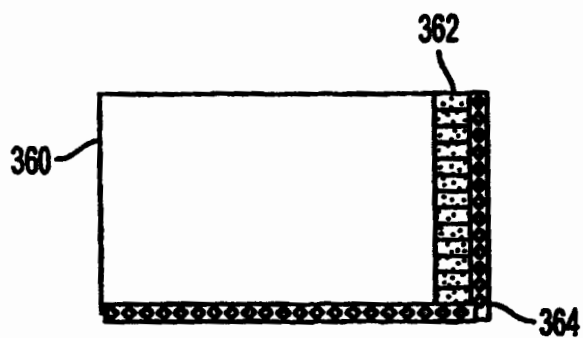


FIG. 36-A

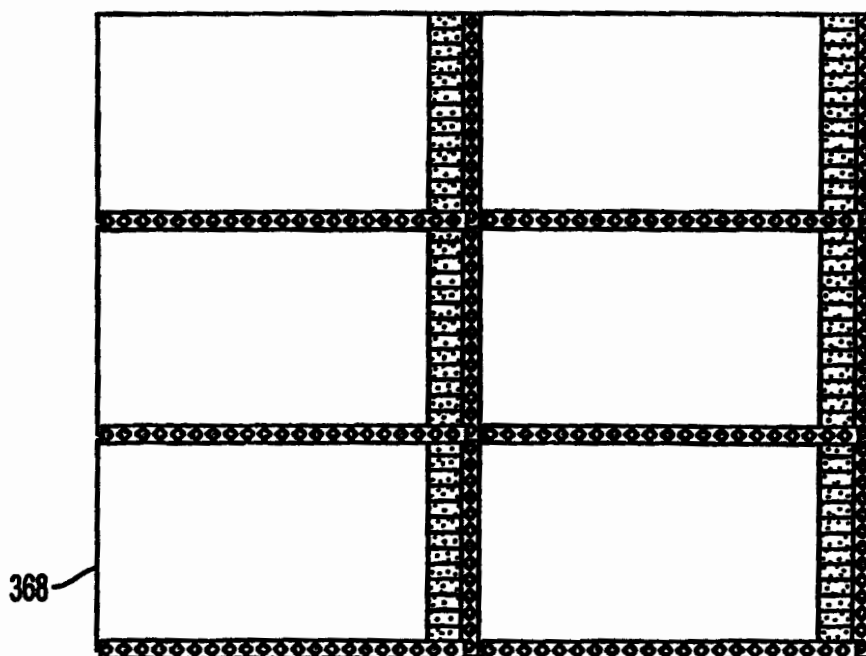


FIG. 36-B

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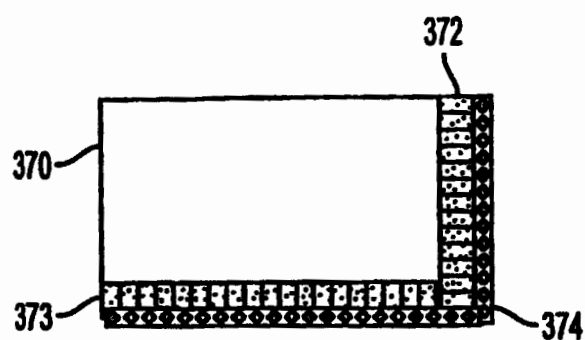


FIG. 37-A

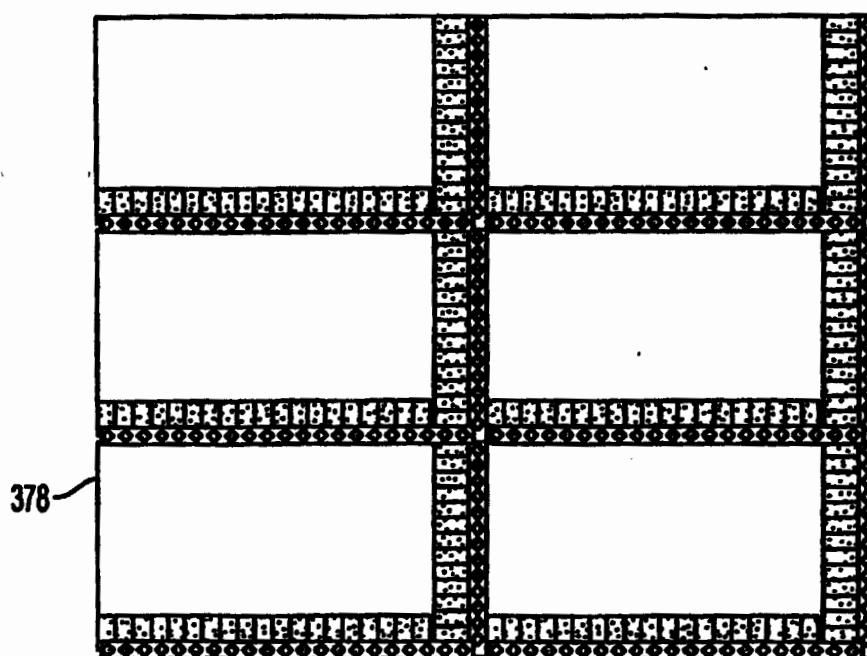


FIG. 37-B

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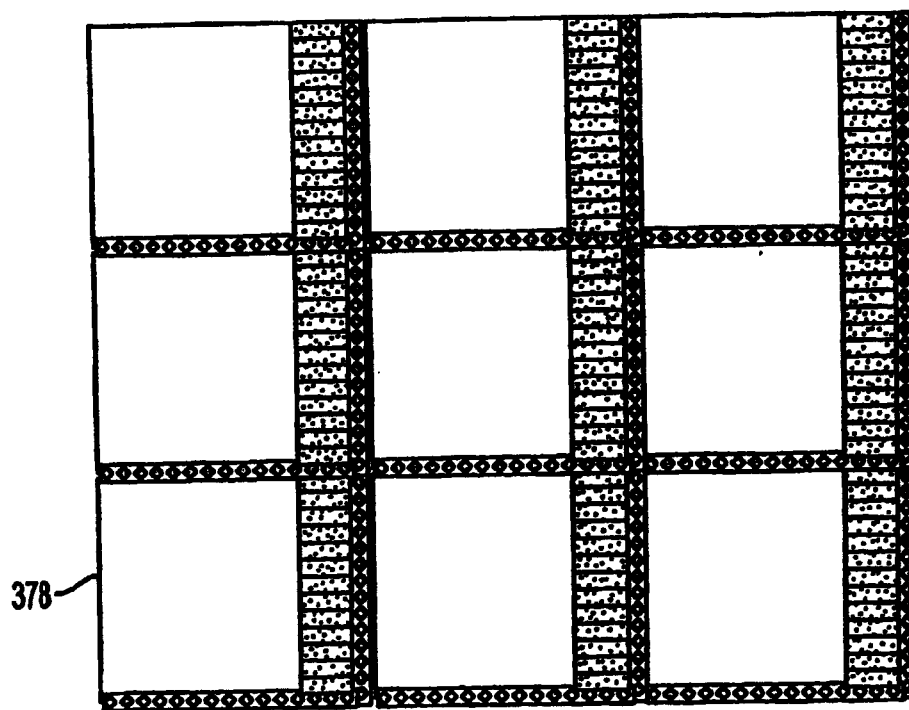
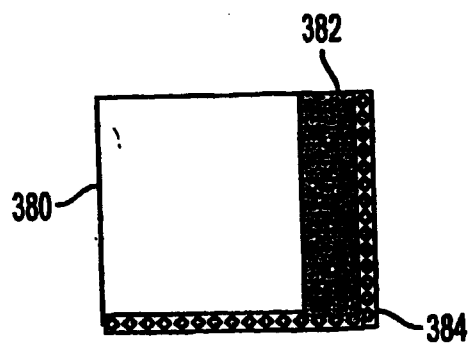


FIG. 38

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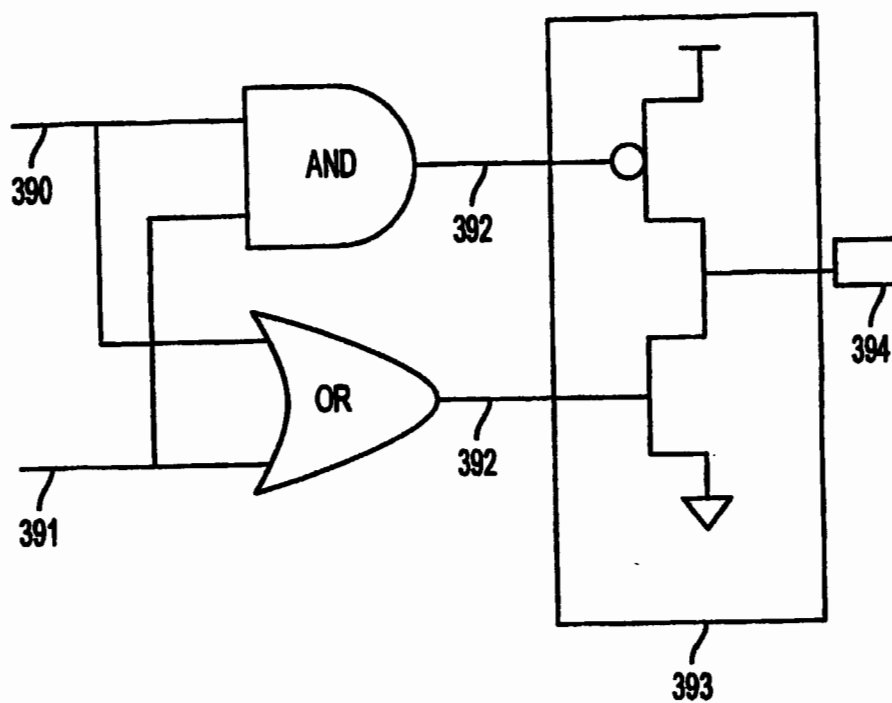


FIG. 39